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AN00093

TJA1020 LIN transceiver

Rev. 02 — 16 September 2005 Application note

Document information

Info	Content
Keywords	TJA1020, Local Interconnect Network (LIN), Transceiver, Physical Layer, ISO 9141
Abstract	The TJA1020 is a low power LIN transceiver for the use in automotive and industrial applications. It supports the single wire bus signal representation being described in the LIN protocol specification for in-vehicle Class-A buses with a single master node and a set of slave nodes. Local Interconnect Network (LIN) is a serial bus protocol being primarily intended for transmission of control related data between a number of bus nodes. This application note provides information how to use the TJA1020 in LIN applications.

PHILIPS

Revision history

Rev	Date	Description
02	20050916	Section 2.5, Section 4.4, Section 5.1 and Section 6 added Section 3.2.1 updated Figure 5, Figure 6 and Figure 32 updated
01	20020128	Preliminary Application Note

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1. Introduction

The Local Interconnect Network (LIN) is a low speed (max. 20 kBaud) class-A, serial bus protocol. A LIN sub-bus is primarily intended for modules like seat, door, roof, switch panel, steering wheel, etc. Its task is to connect switches, actuators and sensors into a sub-bus that links to the main bus e.g. a CAN bus.

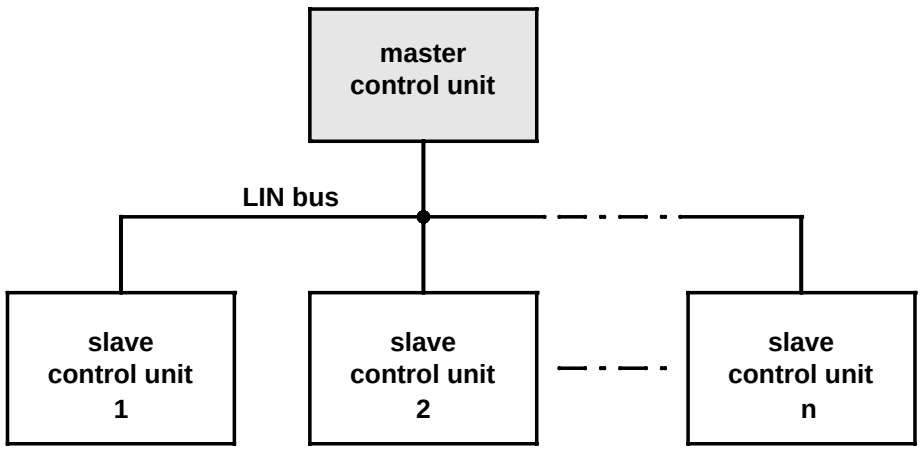


Fig 1. Single-master / multiple-slave concept

The LIN protocol (Ref. 2) is based on the UART/SCI serial data link format using 8N1-coded byte fields. A LIN network consists of one master node and one or more slave nodes; the medium access is controlled by the master node. Such a single-master/multiple-slave concept is shown in Figure 1.

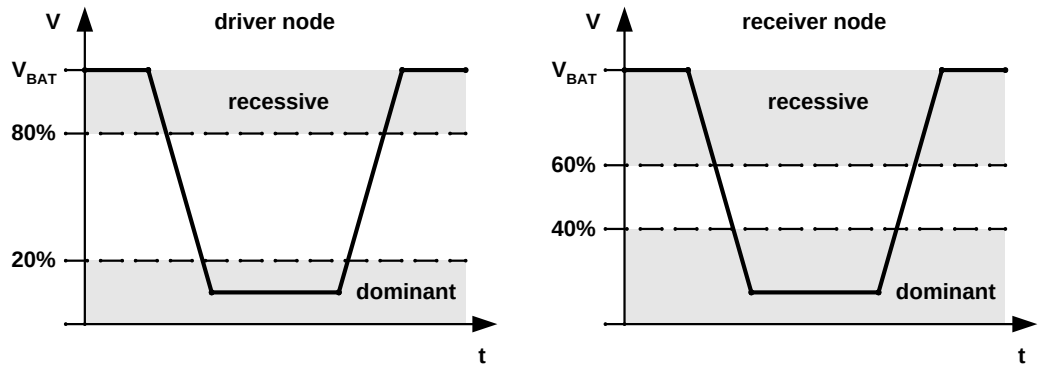


Fig 2. Voltage levels on the LIN bus line

The LIN physical layer has been derived from the ISO 9141 (Ref. 3) standard but has some enhancements to meet the particular operation requirements in automotive environments such as EMC, ESD, etc. The LIN bus is a single-wire, wired AND bus with a 12 V-battery related recessive level. The voltage levels on the LIN bus line are shown in Figure 2.

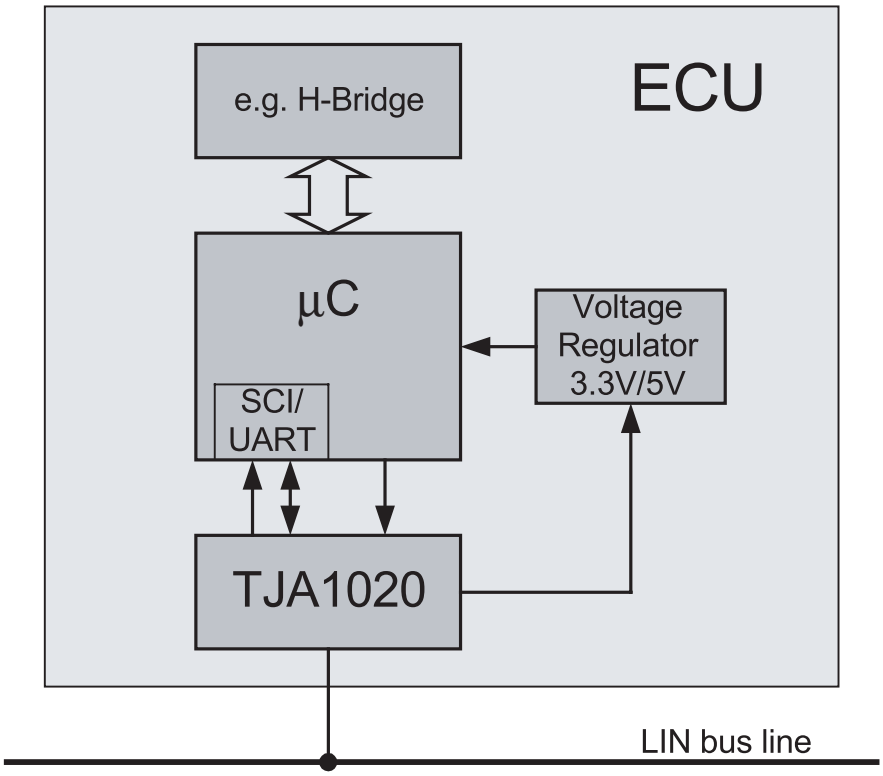


Fig 3. Typical LIN ECU

This report describes the technical implementation of the TJA1020 (Ref. 1) as Physical Medium Attachment within LIN. Its focus is to provide application hints / recommendations for the design of LIN electronic control units (ECUs) using the LIN transceiver TJA1020 from Philips Semiconductors (see Figure 3).

2. General description

The transceiver TJA1020 represents the Physical Medium Attachment, interfacing the LIN master/slave protocol controller to the LIN transmission medium. The transmit data stream of the protocol controller at the TXD input is converted by the LIN transceiver into a bus signal with controlled slew rate and wave shaping to minimize ElectroMagnetic Emission (EME). The receiver of the TJA1020 detects the data stream on the LIN bus line and transmits it via the RXD pin to the protocol controller.

The transceiver provides low-power management (see Section 2.3), consumes nearly no current in Sleep mode (see Section 9.1) and minimizes the power consumption in failure modes (see Section 9.2).

The TJA1020 transceiver is optimized for the maximum specified LIN transmission speed of 20 kBaud and is recommended for networks including up to 16 nodes (Ref. 2).

The pinning of the TJA1020 is chosen to be compatible to standard K-Line transceivers.

2.1 Features

The main features of the TJA1020 are:

- Baud rate up to 20 kBaud
- Very low ElectroMagnetic Emission (EME) due to output wave shaping
- Very high ElectroMagnetic Immunity (EMI)
- Low-slope mode for low speed applications (< 10 kBaud) to reduce EME even further
- Very low current consumption in Sleep mode
- Battery discharge protection in case of LIN to GND short-circuit
- Transmit data (TXD) dominant time-out function
- Wide battery supply operation range, up to jump start conditions (27 V)
- Control input and output levels compatible with devices supplied out of 3 V up to 5 V
- Integrated termination resistor for LIN slave applications
- Local and remote wake-up in Sleep mode
- Recognition of the wake-up source (local or remote)
- Fail-safe behavior in case of unpowered conditions, no reverse current paths
- Bus terminal protected against short-circuits and transients in the automotive environment
- Direct battery operation with protection against load dump, jump start and transients
- No 5 V supply required
- Thermally protected

2.2 Block diagram

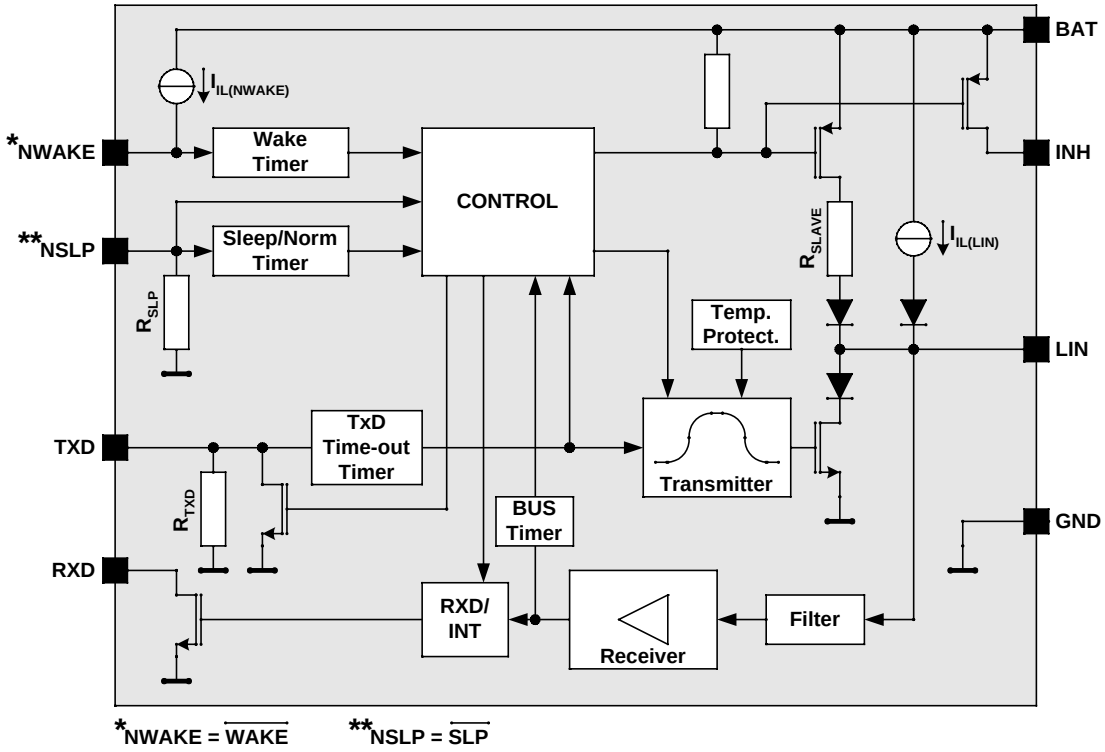


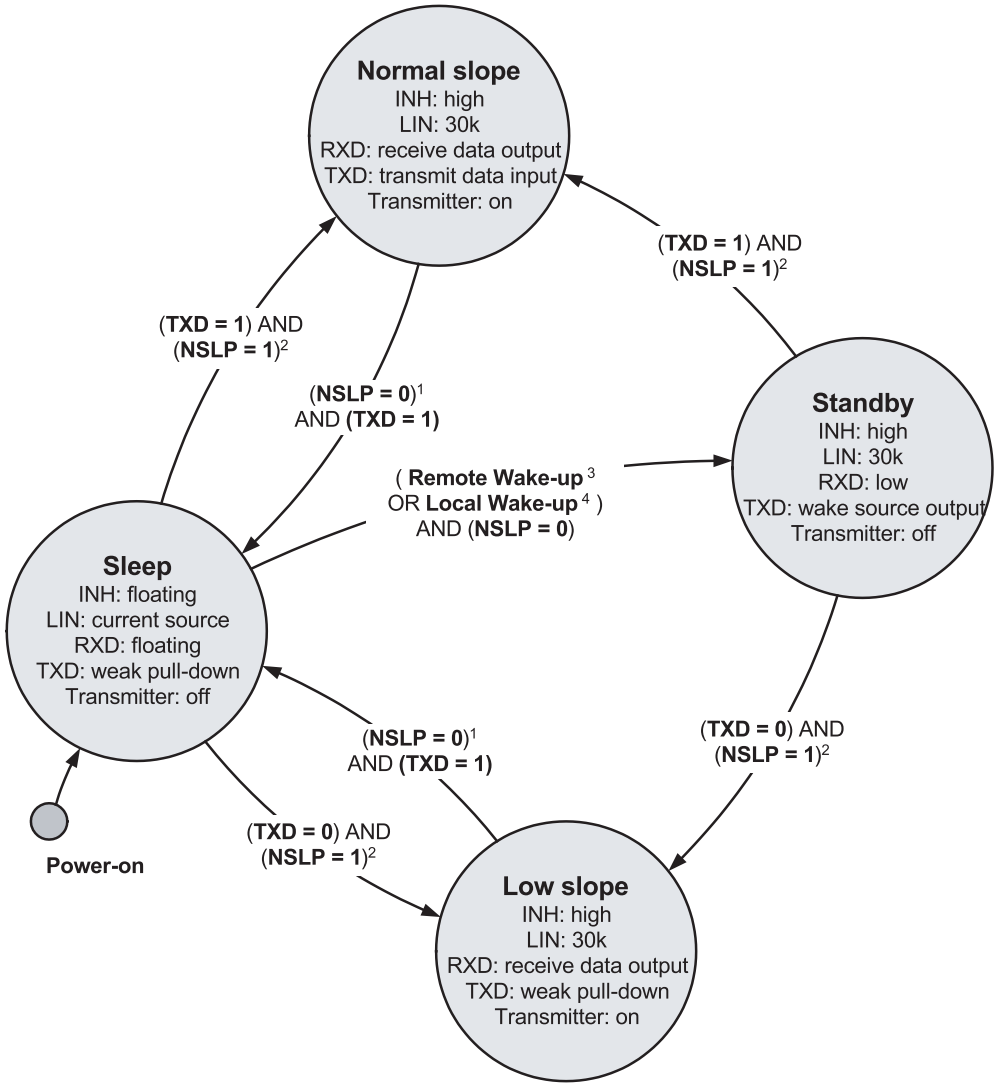
Fig 4. Block diagram of the TJA1020

2.3 Operating modes

The TJA1020 provides four operating modes: Normal-slope mode, Low-slope mode, Standby mode and Sleep mode. The operating modes are shown in Table 1 and Figure 5.

Table 1: Operating modes

Mode	NSLP	TXD	RXD	INH	Trans-mitter	R_{SLAVE}	Remarks
Sleep	0	weak pull-down	floating	floating	off	current source	see Section 2.3.1
Standby	0	weak pull-down if remote wake-up; strong pull-down if local wake-up	low	high (V_{BAT})	off	30 kΩ	see Section 2.3.2
Low-slope	1	weak pull-down	high: recessive state; low: dominant state	high (V_{BAT})	on	30 kΩ	see Section 2.3.4
Normal-slope	1	weak pull-down	high: recessive state; low: dominant state	high (V_{BAT})	on	30 kΩ	see Section 2.3.3



(1) $t_{(NSLP=0)} > t_{gotosleep}$ (Ref. 1)

(2) $t_{(NSLP=1)} > t_{gotonorm}$ (Ref. 1)

(3) LIN becomes dominant for $t_{(LIN=0)} > t_{BUS}$ (Ref. 1) and is followed by an edge to recessive

(4) NWAKE becomes low for $t_{(NWAKE=0)} > t_{NWAKE}$ (Ref. 1)

Fig 5. State diagram of the TJA1020

2.3.1 Sleep mode

The Sleep mode of the TJA1020 provides the lowest achievable power consumption within LIN ECUs. This is achieved by a very low current dissipation of the transceiver itself and switching off the external voltage regulator through the INH output. During Sleep mode the INH output is floating.

Although the power consumption is extremely low, a remote wake-up via LIN and a local wake-up via NWAKE will be recognized and results in a mode change towards Standby mode (see Section 2.3.2). Furthermore the TJA1020 provides direct control of Normal or Low-slope mode via NSLP independently of a previous wake-up event (see Section 2.3.3

and Section 2.3.4). This is useful for applications where the microcontroller supply is not controlled by the INH output and thus, the microcontroller could activate the transceiver at any time.

The TJA1020 is protected against unwanted wake-up events caused by automotive transients or EMI. For this purpose the transceiver provides filters and/or timers at the input of the receiver (LIN), of the local wake-up input (NWAKE) and of the sleep control input (NSLP). Therefore all wake-up events have to maintain for a certain time period (t_{BUS}, t_{WAKE} and $t_{gotonorm}$).

The Sleep mode is entered if a low level at the sleep control input pin NSLP maintains for at least $t_{gotosleep}$ (Ref. 1) (see Figure 6) and no wake-up event (remote or local) happens within this time. This filter time prevents unintended transitions towards Sleep mode caused by EMI. During the mode transition it is recommended to keep TXD on high level to avoid generation of unintended wake-up events on the LIN bus. The activation of the Sleep mode is even possible, if LIN and/or NWAKE are clamped to ground, e.g. caused by a short-circuit to ground.

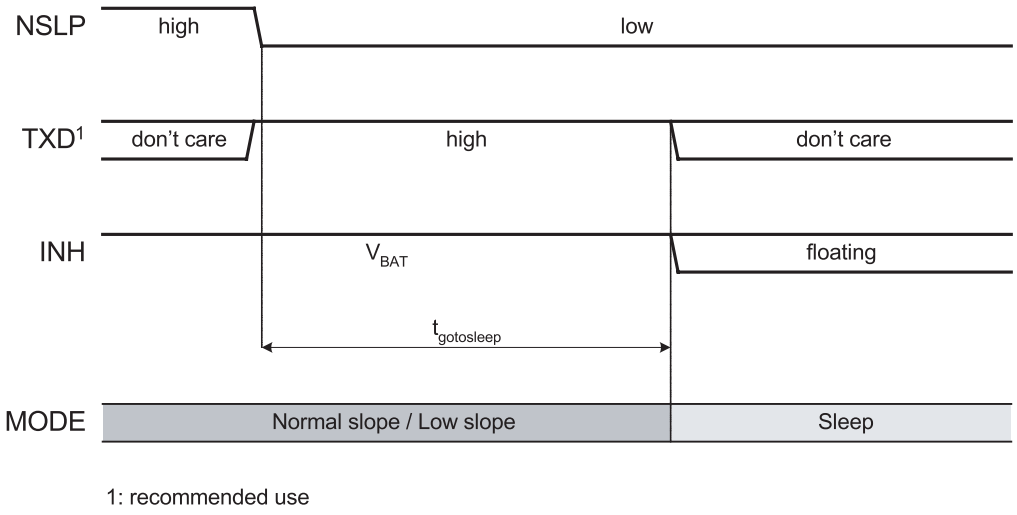


Fig 6. Sleep mode timing

During Sleep mode, the internal slave termination resistor R_{SLAVE} between LIN and BAT is disabled; only a weak current source is present. This minimizes the current consumption in case LIN bus is short-circuited to ground.

2.3.2 Standby mode

The Standby mode is an intermediate mode that is entered only, if a remote or local wake-up occurs while the TJA1020 is in its Sleep mode. In Standby mode the INH pin outputs a battery related high level and therefore can activate an external voltage regulator. In addition the internal slave termination resistor R_{SLAVE} between LIN and BAT is activated.

The TJA1020 signals the Standby mode with a low level at the RXD pin. This can be used as wake-up interrupt request for a microcontroller. Furthermore the wake-up source is signalled by the pull-down condition at the TXD pin. A remote wake-up event results in a

weak pull-down and a local wake-up event results in a strong pull-down at TXD. Depending on the used microcontroller an external pull-up resistor could be necessary (see Section 3.2.2).

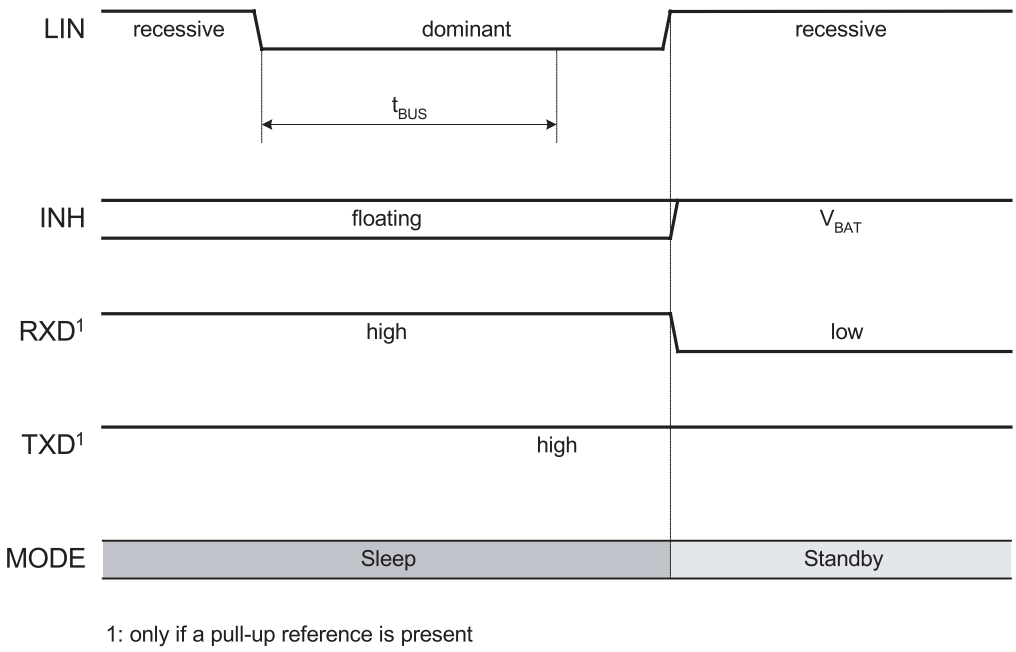


Fig 7. Standby mode timing of remote bus wake-up

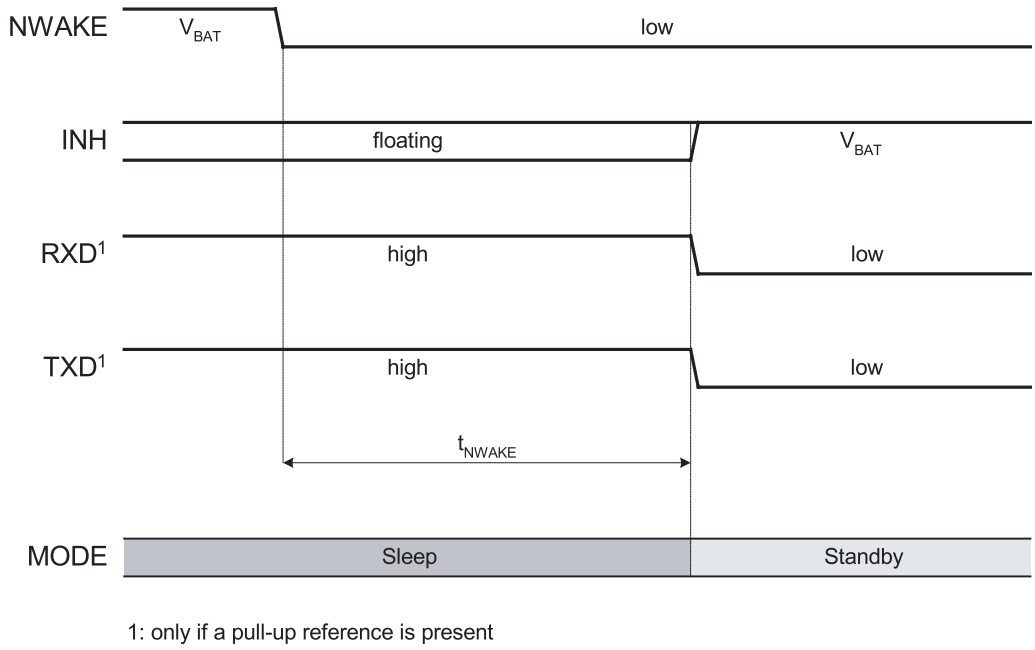


Fig 8. Standby mode timing of local wake-up

Figure 7 and Figure 8 show the timing of a remote and local wake-up and their particular outputs at RXD and TXD. A remote wake-up via LIN bus is detected, if the LIN wire becomes continuously dominant for at least t_{BUS} (Ref. 1) followed by an edge to recessive bus level. A falling edge at the NWAKE pin results in a local wake-up if the low level maintains for at least t_{NWAKE} (Ref. 1).

2.3.3 Normal-slope mode

The Normal-slope mode is used to transmit and receive data via the LIN bus line. The bus data stream is converted by the receiver into a digital bit stream and output at the RXD to the microcontroller. A high level on the RXD pin represents a recessive level on the LIN bus line and a low level on the RXD pin represents a dominant LIN bus line. The transmitter of the TJA1020 converts the data stream of the microcontroller at the TXD input into a wave shaped LIN bus signal to minimize the EME. A low level TXD input results in a dominant LIN bus level while a high level input results in a recessive bus level.

In Normal-slope mode the internal slave termination resistor R_{SLAVE} (Ref. 1) pulls the LIN bus pin high. The INH pin provides a battery related high level to keep an external voltage regulator on.

The Normal-slope mode is entered setting NSLP and TXD high for at least $t_{gotonorm,max}$ (Ref. 1). The mode transition is executed when $t_{gotonorm}$ (Ref. 1) is expired. Figure 9 shows the timing of a transition from Sleep or Standby mode to Normal-slope mode.

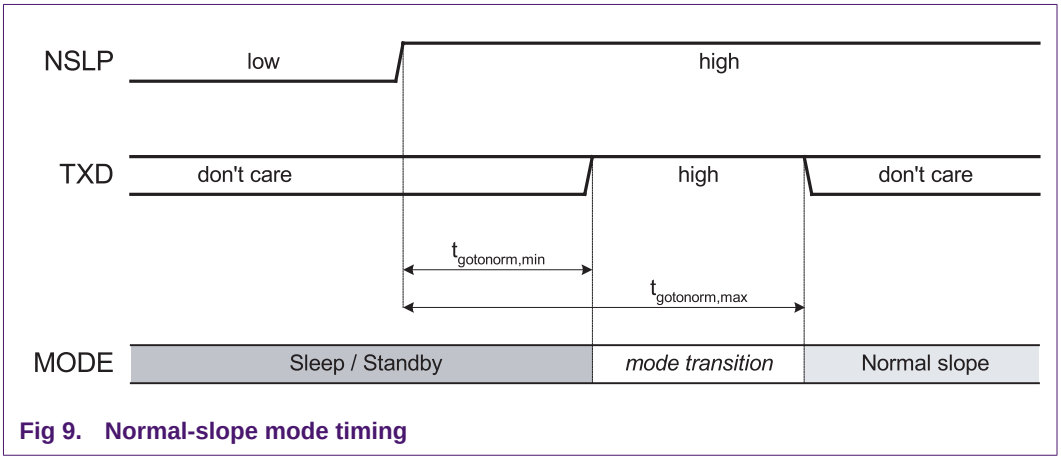


Fig 9. Normal-slope mode timing

2.3.4 Low-slope mode

The Low-slope mode can be used within LIN systems below 10 kBaud and allows a further reduction of the EME compared to the already very low EME of the Normal-slope mode. So the only difference compared to Normal-slope mode is the bus signal transition time. For the Low-slope mode, the transition time is about two times longer than for the Normal-slope mode (see Figure 10).

The Low-slope mode can be entered only coming from the Sleep or Standby mode. A direct transition from Normal-slope to Low-slope mode is not possible.

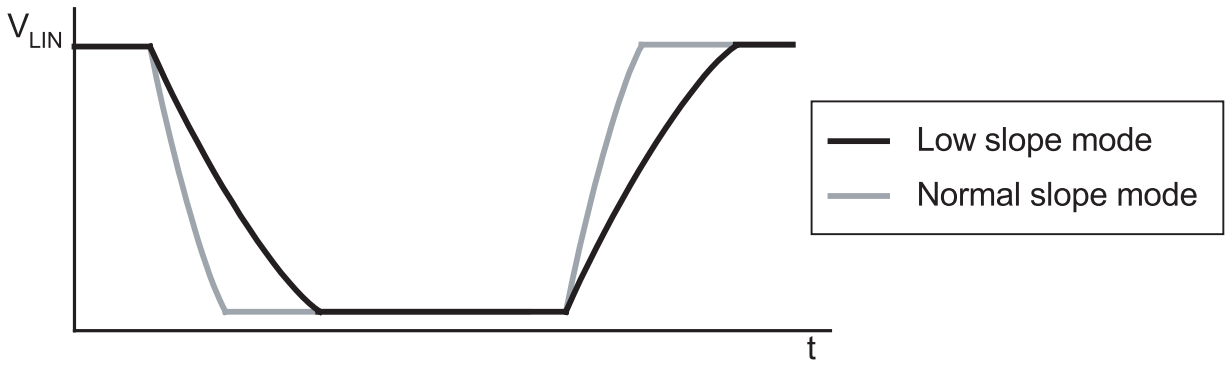


Fig 10. Reduced LIN bus slope in Low-slope mode

The Low-slope mode is entered by a low level on the TXD pin in conjunction with a high level on the NSLP pin maintained for at least $t_{gotonorm,max}$ (Ref. 1). The mode transition is executed when $t_{gotonorm}$ (Ref. 1) is expired. The timing of a transition from Sleep or Standby mode to Low-slope mode is shown in Figure 11.

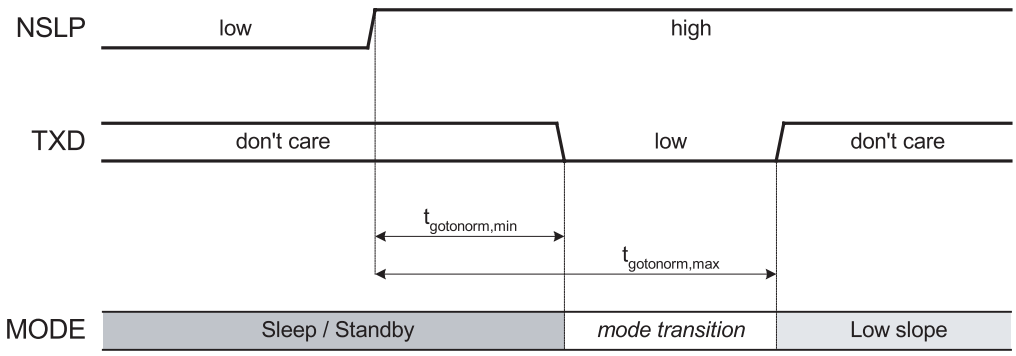


Fig 11. Low-slope mode timing

2.4 Compatibility to 3.0 V to 5 V microcontroller devices

The TJA1020 is designed to support the increasing demand for lower supply voltages than 5 V within automotive applications. It provides reduced input thresholds at the input pins TXD and NSLP and open drains at the output pins RXD and TXD. So it is compatible to 3.0 V/3.3 V supplied microcontroller as well as to 5 V supplied devices. There is no 5 V tolerant behavior of interface pins between the TJA1020 and the host microcontroller needed and furthermore no extra V_{CC} supply for the transceiver itself required.

To achieve a suitable high level at RXD and TXD an external pull-up resistor might be required in case such a pull-up resistor is not part of the microcontroller port pin itself.

2.5 ISO 9141 compatibility

The Standard ISO 9141-2 ‘Road Vehicles – Diagnostic Systems – Part 2’ (Ref. 3) specifies the interchange of digital (diagnostic) information between on-board ECUs of road vehicles and a scan/test tool. The appropriate bus is the so-called ‘K-Line Bus’.

Although the LIN physical layer (Ref. 2) has been derived from the ISO 9141 (Ref. 3) standard it has some differences such as shown in Table 2.

Table 2: Comparison ISO9141 (K-Line) with LIN

Description	ISO9141 (Ref. 3)	LIN (Ref. 2)	Compliance
Operating voltage range V_B	8 V to 16 V	7.3 V to 18 V	√
Receiver high state	> 70 % V_B	> 60 % V_B	√
Receiver low state	< 30 % V_B	< 40 % V_B	√
Temperature range	0 °C to 50 °C	–40 °C to 125 °C	√
Capacitance			
Diagnose tester / LIN master	< 2 nF	-	√
ECU / LIN slave	< 500 pF	< 250 pF	Not compliant! But the TJA1020 can be used with the ISO 9141 ECU capacitance load
Wiring	< 2 nF	< 6 nF	√
Total	< 9.6 nF	< 10 nF	√
Resistance			
Diagnose tester / LIN master	510 Ω	0.9 kΩ to 1.1 kΩ	Not compliant! But the TJA1020 can be used with the ISO 9141 diagnose tester pull-up.
ECU / LIN slave	> 100 kΩ	20 kΩ to 60 kΩ	Not compliant! LIN transceivers are typically implemented with an integrated LIN slave resistor.
Timings			
Transmission rate	10.4 kbit/s	1 kbit/s to 20 kbit/s	√
Slew rate / slope time	< 10 % T_{BIT} = 9.6 µs	0.5 V/µs to 3 V/µs; 3.5 µs to 22.5 µs	Not compliant! The timing of TJA1020 is according to LIN (Ref. 2), which results in better EMC compared to ISO 9141 (Ref. 3).

Although the LIN physical layer is not fully compatible to the ISO standard, in practice a LIN transceiver can be used in K-Line networks. Only the number of K-Line nodes could be limited, if LIN transceivers have been applied. In a K-Line bus the overall network load is mainly caused by the diagnose tester (the master in a K-Line bus (Ref. 3)), which is terminated with a pull-up of R_{TESTER} = 510 Ω. But each LIN transceiver with integrated LIN slave resistor R_{SLAVE}, like the TJA1020, will cause a decrease of the K-Line network resistance. The K-Line network resistance reduction can be calculated with following equation:

Minimum K-Line network load:

$$R_{K(BUS-BAT),min} = \frac{R_{TESTER,min} \times \frac{R_{SLAVE,min}}{N}}{R_{TESTER,min} + \frac{R_{SLAVE,min}}{N}}$$

with

R_{TESTER} = minimum diagnose tester pull-up resistor

$R_{SLAVE,min}$ = minimum LIN slave pull-up resistor

N = number of transceivers with integrated LIN slave resistor

Thus the maximum number of LIN transceivers in a K-Line bus is limited by the strength of the weakest bus driver. The TJA1020 is specified for the minimum network resistance of $R_{L(LIN-BAT)}$ = 500 Ω (Ref. 1). Nevertheless the bus driver of the TJA1020 can drive a lower network resistance. The minimum bus resistance is $R_{L(BUS-BAT),min}$ = 450 Ω, which is derived from the minimum bus driver current limitation $I_{O(SC)}$ (Ref. 1).

Though there are some deviations between the LIN and the ISO 9141 specification, the TJA1020 is able to support the K-Line bus from functional point of view. From a formal point of view, no LIN transceiver supports by 100 % the original ISO 9141-2 specification (Ref. 3).

3. Slave application

3.1 Set-up

A slave application of the LIN transceiver TJA1020 is shown in Figure 12. The protocol controller (e.g. microcontroller) is connected to the LIN transceiver via a UART/SCI based interface or standard I/O port pins. The TXD pin of the TJA1020 is the transmit data input and the RXD pin is the receive data output. The sleep control input NSLP of the LIN transceiver can be controlled by a microcontroller port pin. The TJA1020 provides an internal slave termination resistor. Thus for a slave application no extra LIN bus termination resistor is needed. The capacitor C_{SLAVE} in Figure 12 is recommended in order to improve the EME as well as EMI performance of the LIN system (see also Section 4.4).

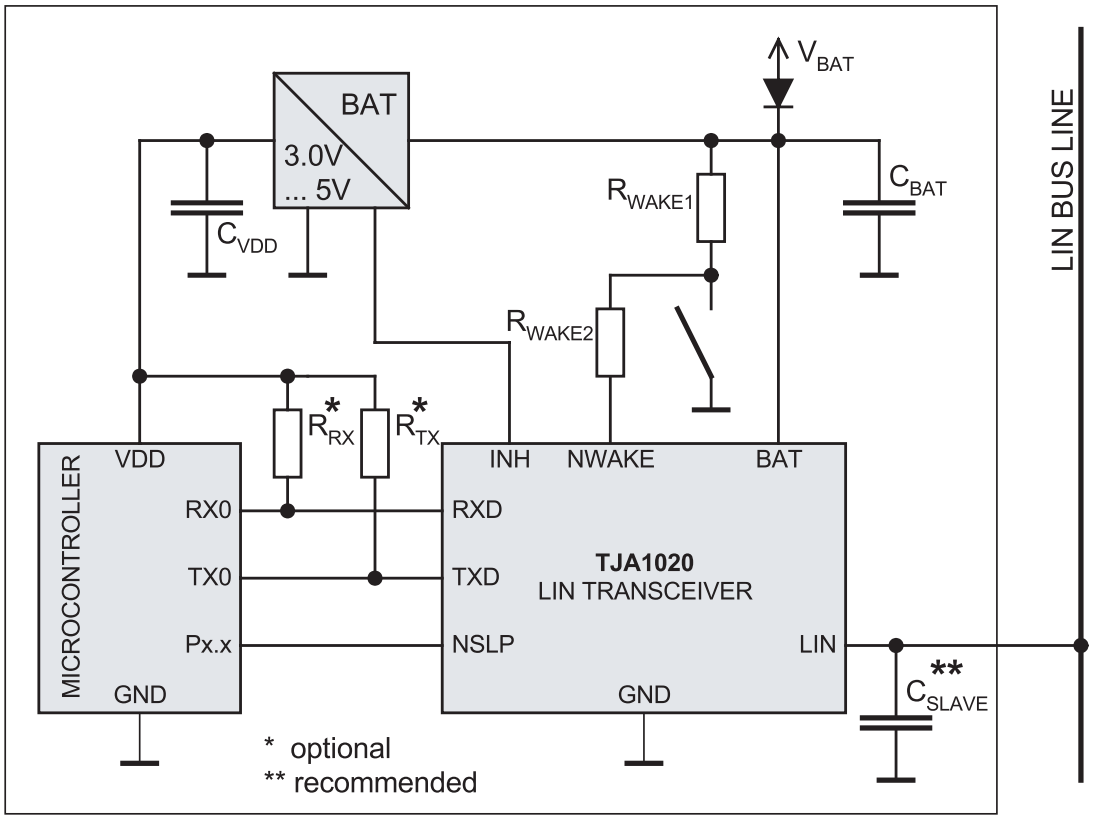


Fig 12. TJA1020 application example

3.2 Detailed pin description

3.2.1 NSLP pin

The sleep control pin NSLP provides an internal pull-down resistor R_{SLP} to support a defined input level in case of open circuit failures. A low level results in the Sleep mode and reduces the power dissipation to a minimum. The range of the input threshold is chosen to support 5 V as well as 3.0 V/3.3 V supplied devices. A typical NSLP pin application is shown in Figure 13.

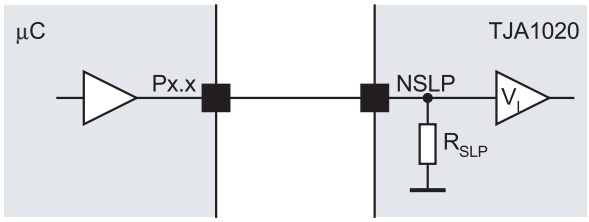


Fig 13. Typical NSLP pin application

The minimum drive capability of the microcontroller port pin for the NSLP pin can be calculated with the following equation:

Min. high level port pin strength at $V_{\mu C} > V_{IH(SLP),min}$:

$$I_{HIGH(\mu C),\,min} = \frac{V_{IH(SLP),min}}{R_{SLP,min}} + I_{IL(SLP),max}$$

with (Ref. 1)

$V_{IH(SLP),min}$ = minimum NSLP HIGH-level input voltage

$R_{SLP,min}$ = minimum NSLP pull-down resistor

$I_{IL(SLP),max}$ = maximum NSLP LOW-level input current

The LIN slope operation modes (see Section 2.3), such as Normal and Low-slope mode, depend on NSLP and TXD. Hence, it is recommended to connect NSLP to a microcontroller port pin. Due to the undefined power-on rise timing between TXD and a V_{CC} source, NSLP connected to a V_{CC} source would result in an undefined LIN slope operation mode. Therefore, it is dissuaded to connect NSLP directly to a V_{CC} supply source.

3.2.2 TXD pin

3.2.2.1 Wake-up source recognition

The TXD pin is a bi-directional pin. In Normal-slope and Low-slope mode it is used as transmit data input whereas in Standby mode the wake-up source is signalled. Here an active low output of the TXD pin indicates a local wake-up event on the NWAKE pin. If a local wake-up source at the NWAKE pin is used, a pull-up behavior at pin TXD is required. This pull-up can be achieved in two ways:

1. The microcontroller port pin provides an integrated pull-up $R_{TX(\mu C)}$ (see Figure 14a)
2. An external pull-up resistor $R_{TX(ext)}$ towards the local V_{CC} is connected (see Figure 14b)

In case no local wake-up source is present (NWAKE is unused), no external pull-up resistor is required. Then TXD will never be pulled to a strong low level by the TJA1020.

If the local wake-up feature (NWAKE) of the TJA1020 is used, the required pull-up strength of the external pull-up R_{TX} is defined by:

1. The drive capability of the integrated wake-up source transistor pulling TXD to low in case of a local wake-up event and
2. The integrated TXD pull-down resistor R_{TXD} (Ref. 1) of the TJA1020

The required strength of the microcontroller port pin as well as the value of the pull-up resistor R_{TX} can be calculated by the following equations:

Min. high level pull-up current at $V_{TX(\mu C)} > V_{IH(TXD),min}$:

$$I_{HIGH(RTX),min} = \frac{V_{IH(TXD),min}}{R_{TXD,min}} + I_{IL(TXD),max}$$

Max. low level pull-up current at $V_{TX(uC)} < V_{IL(TXD),max}$:

$$I_{LOW(RTX),max} = \frac{V_{IL(TXD),max}}{V_{TXD}} I_{OL(TXD),min}$$ with V_{TXD} = 0.4 V

Range of pull-up resistor:

$R_{TX,min} < R_{TX} < R_{TX,max}$ with

$$R_{TX,min} = \frac{VCC_{max} - V_{IL(TXD),max}}{I_{LOW(RTX),max}}$$ and $$R_{TX,max} = \frac{VCC_{min} - V_{IH(TXD),min}}{I_{HIGH(RTX),min}}$$

with (Ref. 1)

$V_{IH(TXD),min}$ = minimum TXD HIGH-level input voltage

$V_{IL(TXD),\ max}$ = maximum TXD Low-level input voltage

$R_{TXD,min}$ = minimum TXD pull-down resistor

$I_{IL(TXD),max}$ = maximum TXD LOW-level input current

$I_{OL(TXD),min}$ = minimum TXD LOW-level output current

Remark: For LIN the signal symmetry of the falling and rising transition on TXD has an impact on the overall system tolerances. Thus it is recommended to keep the RC-load time constant on the TXD input as small as possible.

Example: If the supply voltage of the microcontroller ($V_{CC} = V_{CCmin} = V_{CCmax}$) is 5 V, then the range of the pull-up resistor R_{TX} is:

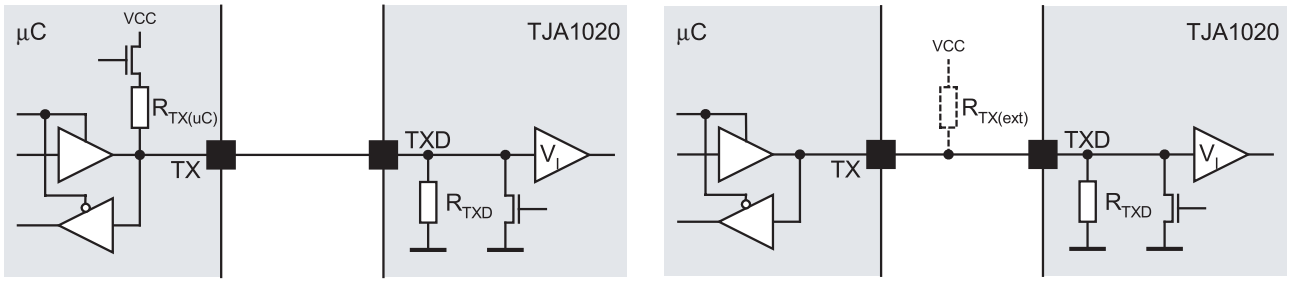
$$R_{TX,min} = \frac{VCC_{max} - V_{IL(TXD),max}}{I_{LOW(RTX),max}} = 1.4\ k\Omega$$ with

$$I_{LOW(RTX),max} = \frac{V_{IL(TXD),max}}{V_{TXD}} I_{OL(TXD),min} = 3\ mA$$

$$R_{TX,max} = \frac{VCC_{min} - V_{IH(TXD),min}}{I_{HIGH(RTX),min}} \approx 140\ k\Omega$$ with

$$I_{HIGH(RTX),min} = \frac{V_{IH(TXD),min}}{R_{TXD,min}} + I_{IL(TXD),max} = 21\ \mu A$$

A recommended value for the pull-up resistor R_{TX} is 2.2 kΩ.



a. for µC with internal programmable pull-up

b. for µC without internal pull-up

Fig 14. Typical TXD pin application

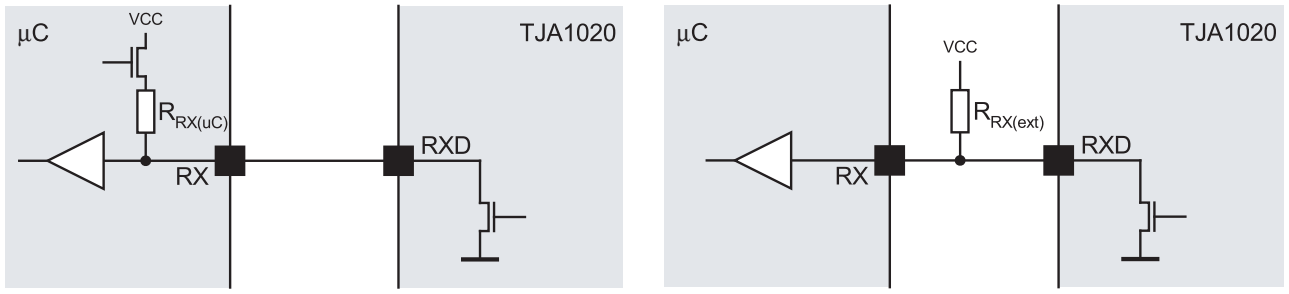
The open drain output as well as the maximum value of the input threshold $V_{IH(TXD)}$ (Ref. 1) are designed to support 3.0 V/3.3 V as well as 5 V microcontroller derivatives. Thus 3.0 V/3.3 V microcontroller derivatives without 5 V tolerant ports can be used for the TJA1020.

3.2.2.2 Open circuit handling

The TXD pin provides an internal weak pull-down resistor R_{TXD} (Ref. 1) to ensure a defined input level in case of open circuit failures. Although this TXD input level is dominant, the TXD dominant time-out function prevents the LIN bus from being clamped to a dominant level by disabling the transmitter. Furthermore the weak pull-down allows providing an output level free TXD pin.

3.2.3 RXD pin

The receive data output RXD provides an open drain behavior in order to get an output level, which can be adapted to the microcontroller supply voltage. Thus 3.0 V/3.3 V microcontroller derivatives without 5 V tolerant ports can be used. In case the microcontroller port pin does not provide an integrated pull-up, an external pull-up resistor connected to the microcontroller supply voltage V_{CC} is required. In Figure 15 typical RXD applications are shown.



a. for µC with internal programmable pull-up

b. for µC without internal pull-up

Fig 15. Typical RXD pin application

The minimum pull-up resistor $R_{RX,min}$ is defined by the drive capability of the TJA1020's RXD output pin. The maximum pull-up resistor $R_{RX,max}$ depends on the maximum delay of the rising edge $t_{rPropRX}$ caused by the RC-load on RXD:

Range of pull-up resistor:

$R_{RX,min} < R_{RX} < R_{RX,max}$ with

$$R_{RX,min} = \frac{VCC_{max} - V_{LOW(RX),max}}{V_{LOW(RX),max}} \times \frac{V_{RXD}}{I_{OL(RXD),min}},\ V_{RXD} = 0.4\ V \text{ and}$$

$$R_{RX,max} = \frac{t_{rPropRX,max}}{(C_{RX(ext),max} + C_{RX(\mu C),max} + C_{RXD,max}) \times 1n\left(\frac{VCC_{min}}{VCC_{min} - V_{HIGH(RX),min}}\right)},$$

where $R_{RX,max} \leq \frac{VCC_{min} - V_{HIGH(RX),min}}{I_{LH(RXD),max}}$, $t_{rPropRX,max} = 3\ \mu s$ and $C_{RXD,max} = 5\ pF$

with

$I_{LH(RXD),max}$ = maximum RXD HIGH-level leakage current (Ref. 1)

$I_{OL(RXD),min}$ = minimum RXD LOW-level output current (Ref. 1)

$V_{HIGH(RX),min}$ = minimum µC port pin (RX) HIGH-level input voltage

$V_{LOW(RX),max}$ = maximum µC port pin (RX) LOW-level input voltage

$C_{RX(\mu C),max}$ = maximum µC port pin (RX) capacitance

$C_{RX(ext),\ max}$ = maximum external capacitance

Remark: For LIN the signal symmetry of the falling and rising transition on RXD has an impact on the overall system tolerances. Thus it is recommended to keep the RC-load time constant on the RXD output as small as possible, but due to the driver strength of the RXD output the pull-up resistor R_{RX} should not be below 1 kΩ.

Example: If the supply voltage of the microcontroller ($V_{CC} = V_{CCmin} = V_{CCmax}$) is 5 V, the microcontroller port input threshold voltage range is from $V_{LOW(RX),max}$ = 0.8 V to $V_{HIGH(RX),min}$ = 2 V and the microcontroller port capacitance is $C_{RX,max} = C_{RX(\mu C),max} + C_{RX(ext),max}$ = 15 pF, then the range of the pull-up resistor R_{RX} is:

$$R_{RX,min} = \frac{VCC_{max} - V_{LOW(RX),max}}{V_{LOW(RX),max}} \times \frac{V_{RXD}}{I_{OL(RXD),min}} = 1.4\ k\Omega$$

$$R_{RX,max} = \frac{t_{rPropRX,max}}{(C_{RX,max} + C_{RXD,max}) \times ln\left(\frac{VCC_{min}}{VCC_{min} - V_{HIGH(RX),min}}\right)} \approx 290\ k\Omega$$

$$R_{RX,max} = 290\ k\Omega \leq \frac{VCC_{min} - V_{HIGH(RX),min}}{I_{LH(RXD),max}} \approx 600\ k\Omega$$

A recommended value for the pull-up resistor R_{RX} is 2.2 kΩ in order to keep the RC-load time constant low at the RXD pin.

3.2.4 NWAKE pin

The local wake-up input NWAKE is used to detect local wake-up events using a falling edge. This falling edge has to be followed by a continuous low level of at least t_{NWAKE} in order to successfully pass the integrated EMI filter. The NWAKE pin provides an internal weak pull-up current source $I_{IL(NWAKE)}$ (Ref. 1) towards battery, which defines a high pin level in case of open circuit failures. It is recommended to connect an external pull-up resistor R_{WAKE1} to provide sufficient current for an external wake-up switch or transistor. In

case the wake-up source (switch or transistor) at NWAKE has a different ground path than the TJA1020, it is recommended to add a series resistor R_{WAKE2} between the NWAKE pin and the wake-up source. If the ECU has lost its ground while the wake-up source is still connected to ground, the series resistor R_{WAKE2} protects the ECU against a reverse current supply through the internal protection diodes of NWAKE. Figure 16a shows a typical NWAKE pin application for local wake-up via external switch.

The pull-up resistor R_{WAKE1} depends only on the required current of the wake-up source (switch or transistor), whereas the series resistor R_{WAKE2} is mainly defined by the applications ground shift between the ECU and the external wake-up source. The following equations show how to calculate the recommended series resistor:

Range of series resistor:

$$R_{wake2,min} < R_{WAKE2} < R_{WAKE2,max} \text{ with } R_{WAKE2,min} = \frac{V_{BAT,max}}{I_{NWAKE,min}} \text{ and}$$

$$R_{WAKE2,max} = \frac{V_{IL(NWAKE),max} - |V_{GND-shift}|}{I_{IL(NWAKE),min}} \text{ with e.g. } V_{GND-shift} = 1.5\ V$$

with (Ref. 1)

$V_{IL(NWAKE),max}$ = maximum NWAKE LOW-level input voltage

$I_{IL(NWAKE),min}$ = minimum NWAKE pull-up current

$I_{NWAKE,min}$ = minimum NWAKE output current (limiting value)

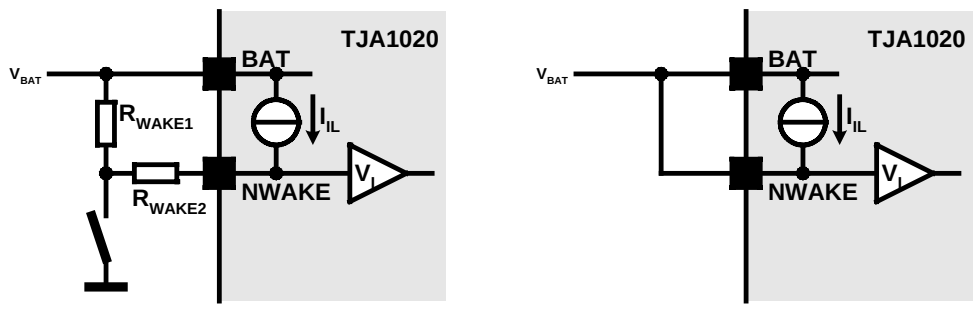
Example: For a maximum ground-shift of $V_{GND-shift}$ = 1.5 V and a battery voltage range of V_{BAT} = 5 V to 27 V is the range of R_{WAKE2}:

$$R_{WAKE2,min} = \frac{V_{BAT,max}}{I_{NWAKE,min}} = 1.8\ k\Omega$$

$$R_{WAKE2,max} = \frac{V_{IL(NWAKE),max} - |V_{GND-shift}|}{I_{IL(NWAKE),min}} \approx 6.6\ k\Omega$$

Therefore a typical value for the series resistor R_{WAKE2} is 3 kΩ.

If no local wake-up is required for the application the NWAKE pin can be left open, due to the internal pull-up and filter behavior. Nevertheless it is recommended to connect the NWAKE pin directly to the BAT pin (see Figure 16b), if not used.



a. for local wake-up via external switch

b. for applications without local wake-up

Fig 16. Typical NWAKE pin application

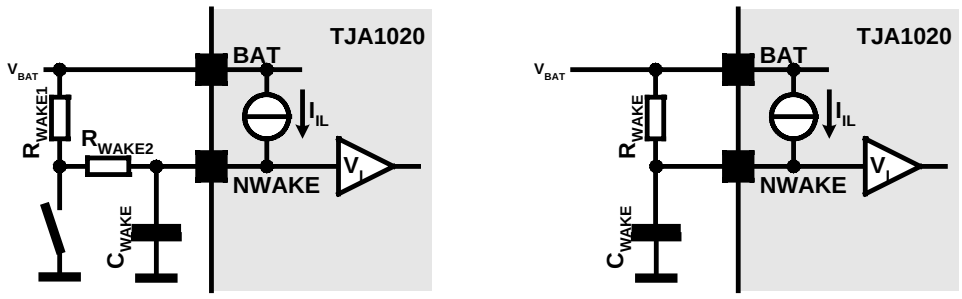
The TJA1020 provides also hardware compatibility to other LIN transceiver implementations, which have a V_{CC} supply input instead of a local wake-up input at pin 3. Therefore the wake-up threshold of the NWAKE input is defined to be above 5 V. Thus this pin can be connected to the applications V_{CC} supply without forcing a wake-up event in case V_{CC} drops down (e.g. system Sleep mode). Nevertheless this would cause a small extra current consumption $I_{IL(NWAKE)}$ (Ref. 1) (internal weak current source) of the system.

3.2.4.1 Wake-up after power-on

After power-on the TJA1020 enters directly the Sleep mode keeping INH on floating condition and thus the supply of the LIN node disabled. This behavior reduces the total power-on peak current of a LIN sub-system.

Nevertheless in some applications a LIN node needs to be waked up autonomously after powering-up. This can be achieved with a RC-combination on NWAKE (see Figure 17b). During power-on such an RC-combination can generate a local wake-up by keeping the NWAKE input voltage V_{NWAKE} below $V_{IL(NWAKE),max}$ (Ref. 1) for at least $t_{NWAKE,max}$ (Ref. 1).

The circuit in Figure 17a provides a solution for both, a local wake-up via external switch and an autonomous wake-up after power-on. For the calculation of R_{WAKE1} and R_{WAKE2} see Section 3.2.4.



a. for local wake-up via external switch b. for applications without local wake-up

Fig 17. Typical NWAKE pin application to wake-up after power-on

Figure 18 shows the relation between the battery voltage V_{BAT} and the resulting NWAKE voltage V_{NWAKE} during power-on, and it shows its constraints to wake-up the TJA1020. The RC-combination can be calculated by the following rule:

RC time constant to wake-up after power-on:

$$R_{WAKE} \times C_{WAKE} = t_{BAT-ON,max} > 2t_{NWAKE,max}$$

with

$t_{NWAKE,max}$ = maximum dominant time to wake-up via NWAKE (Ref. 1)

$t_{BAT-ON,max}$ = maximum power-on ramp-up time of V_{BAT}

Example: Assuming the maximum power-on ramp-up time $t_{BAT-ON,max}$ is 1 ms and the pull-up resistor R_{WAKE} should be 10 kΩ, then C_{WAKE} is:

$$C_{WAKE} = \frac{t_{BAT-ON,max}}{R_{WAKE}} = 100\ nF \text{ with } t_{BAT-ON,max} = 1\ ms > 2t_{NWAKE,max} = 100\ \mu s$$

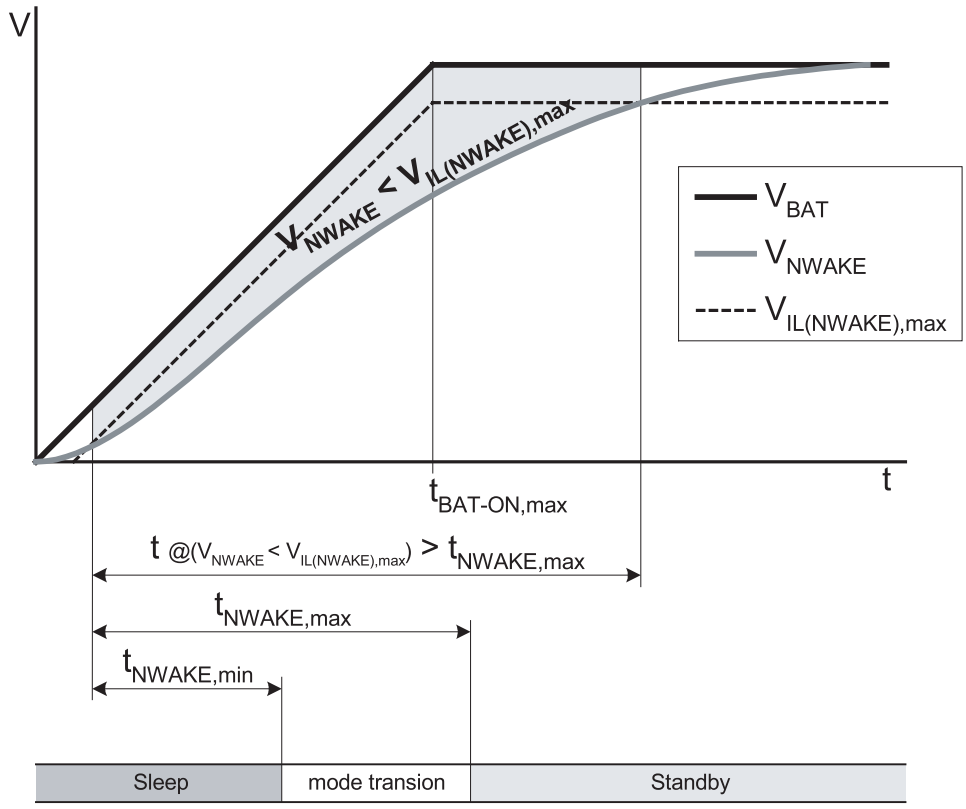
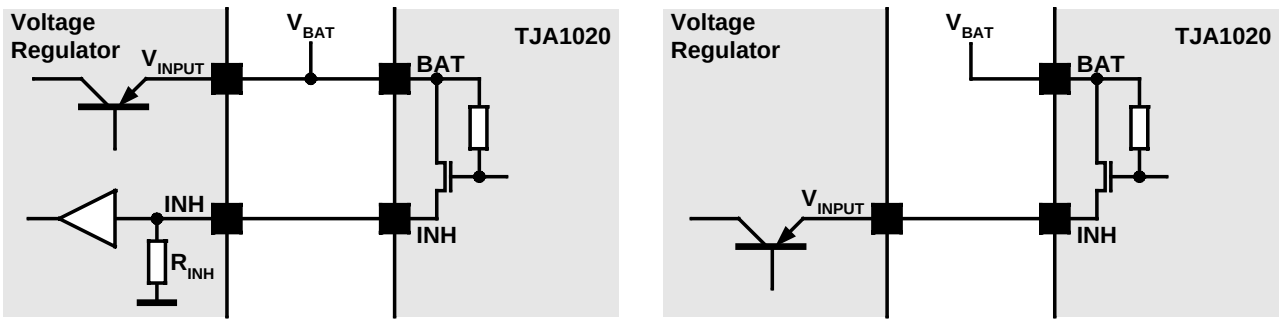


Fig 18. Timing to wake-up after power-on

3.2.5 INH pin

3.2.5.1 INH controlled voltage regulator

The output pin INH is a battery related open drain output to control an external voltage regulator. Therefore an external pull-down resistor R_{INH} connected to ground is necessary. This pull-down is typically integrated within the voltage regulator itself. A typical INH pin application is shown in Figure 19a.



a. for voltage regulators with inhibit input

b. for voltage regulators without inhibit input

Fig 19. Typical INH pin application

The range of the pull-down resistor R_{INH} can be calculated with the equations below:

Range of pull-down resistor:

$$R_{INH,min} < R_{INH} < R_{INH,max} \text{ with } R_{INH,min} = \frac{V_{BAT,max}}{I_{INH,max}}$$ for $I_{INH,max}$ see Section 3.2.5.2.

$$R_{INH,max} = \frac{V_{LOW(VoltReg),max}}{I_{LH(INH),max}}$$

with

$I_{LH(INH),max}$ = maximum INH HIGH-level leakage current (Ref. 1)

$V_{LOW(VoltReg),max}$ = maximum inhibit LOW-level input voltage (volt regulator)

3.2.5.2 Direct voltage regulator supply

Due to the INH drive capability, the TJA1020 is able to supply a voltage regulator directly. Figure 19b shows the typical INH pin application of such a slave application.

The maximum supply current through the INH pin $I_{INH,max}$ for the voltage regulator and the maximum voltage drop V_{DROP} can be calculated by the equations below:

Max. voltage regulator supply current through INH:

$$I_{INH,max} = \sqrt{\frac{P_{max} - P_{Q,max} - P_{TX,max}}{R_{SW(INH),max}}} \text{ with } I_{INH,max} \leq 50\ mA$$

$$P_{max} = \frac{T_{vj,max} - T_{amb,max}}{R_{th(j-a)}}$$

Max. voltage drop at INH:

$$V_{DROP} = R_{SW(INH),max} \times I_{INH,max}$$

with

$P_{Q,max}$ = maximum quiescence power dissipation (Normal-slope mode, bus recessive, $V_{INH} = V_{BAT}$), see Figure 20

$P_{TX,max}$ = maximum transmitter power dissipation (Normal-slope mode, transmission duty cycle = 50 %, $V_{INH} = V_{BAT}$), see Figure 20

$R_{SW(INH),max}$ = maximum switch-on resistance between BAT and INH (Ref. 1)

and

$T_{vj,max}$ = maximum virtual junction temperature (K) (Ref. 1)

$T_{amb,max}$ = maximum ambient temperature (K)

$R_{th(j-a)}$ = thermal resistance (K/W) (Ref. 1)

Remark: Independently from the above calculation the current through the INH pin I_{INH} should not exceed 50 mA.

The power dissipation depends on the supply voltage V_{BAT} and the baud rate. Figure 20 shows the quiescence power dissipation P_Q and the transmitter power dissipation P_{TX} of the TJA1020 as the function of the supply voltage V_{BAT}. A worst case duty cycle of 50 % and a worst case LIN bus load (R_L = 500 Ω, C_L = 10 nF) are used for the transmitter power dissipation P_{TX} in Figure 20.

The thermal resistance $R_{th(j-a)}$ (Ref. 1) is the ability of an IC package to conduct heat to its environment and is typically specified for free air conditions. Within real applications the use of large copper planes attached to pin GND can reduce the thermal resistance and therefore increase the maximum INH current $I_{INH,max}$.

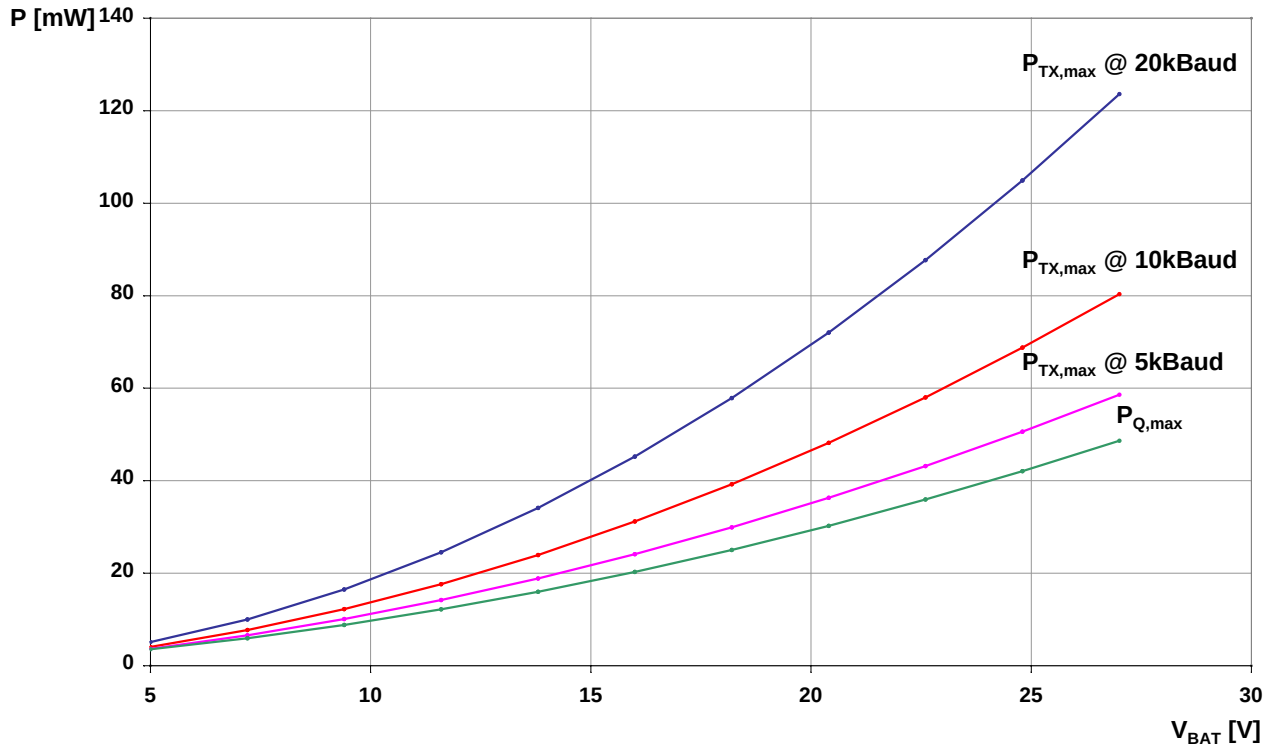


Fig 20. Power dissipation in Normal-slope mode

3.2.6 LIN pin

The pin LIN is used to transmit and receive data on the LIN bus line. A low side switch with controlled wave shaping is used for bit transmission while an integrated receive comparator (receiver) converts the LIN bus voltage back to a binary signal. The threshold of the receiver $V_{th(rx)}$ (Ref. 1) is battery related and has a hysteresis of $V_{thr(hys)}$ (Ref. 1).

The LIN pin has a weak pull-up current source of $I_{IL(LIN)}$ (Ref. 1) and a slave termination resistor of R_{SLAVE} (Ref. 1) in parallel to BAT. The slave termination resistor and the current source as well as the low side switch are implemented with a reverse current diode (see also Figure 21). Thus no external components are required. Nevertheless, improvement of EME and EMI can be achieved by applying a capacitive load at the LIN bus line as shown in Figure 12.

The current source of $I_{IL(LIN)}$ (Ref. 1) is used as an additional weak pull-up, because the slave termination resistor R_{SLAVE} (Ref. 1) is switched off in Sleep mode. Thus a transition into the Sleep mode minimizes the current consumption in case of LIN short-circuit to ground (see Section 9.2).

4. Master application

A master application differs from a slave application mainly with respect to the external master termination resistor R_{MASTER} (Ref. 2). The capacitance load C_{MASTER} (Ref. 2) is recommended in order to improve EME as well as EMI (see also Section 4.4). The TJA1020 provides several master application solutions, which are described in Section 4.1 to Section 4.4.

4.1 Master termination directly to BAT

This master application is realized by a reverse current diode in series with the resistor R_{MASTER} (Ref. 2) connected between LIN and BAT as shown in Figure 21.

Such a master application solution does not provide fail-safe system behavior in case the LIN bus is erroneously shorted to ground. This short-circuit current cannot be switched off, and will discharge the battery continuously.

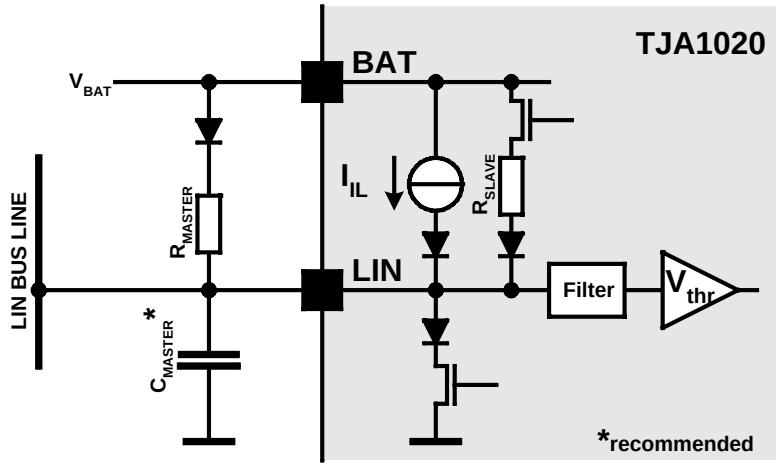


Fig 21. Typical master termination

4.2 Master termination towards INH

For fail-safe reasons the TJA1020 supports an advanced master application solution using the INH pin to drive the master termination resistor R_{MASTER} (Ref. 2). As shown in Figure 22 the master termination resistor in series with a reverse current diode is connected to the INH pin instead of the BAT pin. The advantage of this application solution is the ability to switch off the master termination by a transition into the Sleep mode, thus solving the above mentioned short-circuit condition of LIN and ground.

Whenever the applications microcontroller detects a permanent dominant level on the LIN bus line caused by a ground short-circuit, the microcontroller is able to minimize the power dissipation by selecting the Sleep mode. Thus a transition into the Sleep mode switches off the external voltage regulator, the master termination R_{MASTER} (Ref. 2) as well as the internal slave termination R_{SLAVE} (Ref. 1). Only the internal weak pull-up current source $I_{IL(LIN)}$ (Ref. 1) and the internal current consumption of the TJA1020 determine the remaining current consumption of a LIN node in such a failure case (see also Section 9.2).

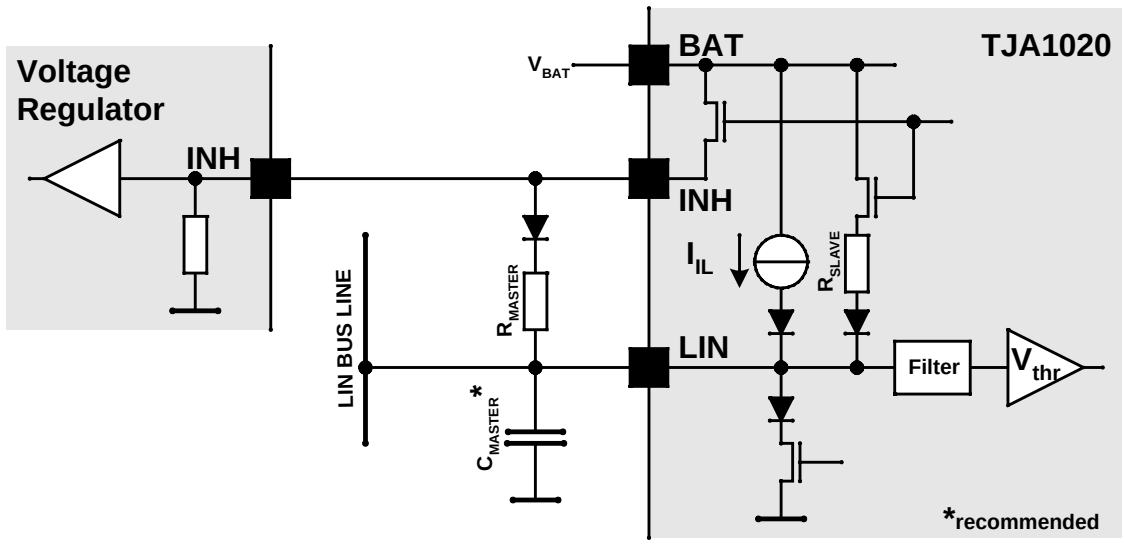


Fig 22. Advanced master termination through the INH pin

4.3 Master termination split between INH and BAT

Since the advanced master termination in Section 4.2 provides a fail-safe system behavior but high LIN bus impedance in Sleep mode, a combination of the terminations concepts in Section 4.1 and Section 4.2 can be an option, if a higher short-circuit current at the LIN bus can be tolerated (see Figure 23).

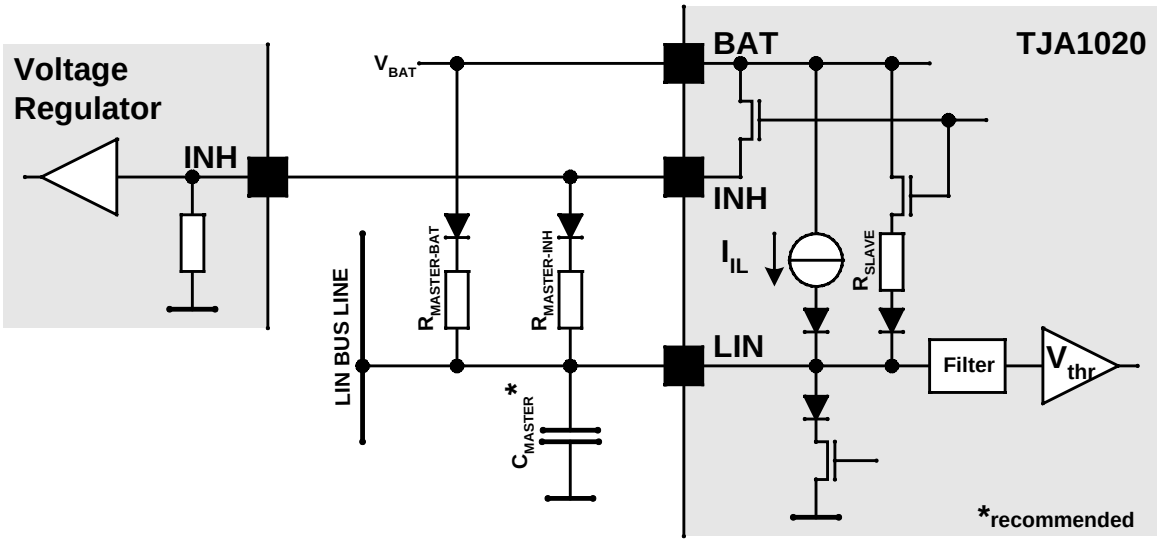


Fig 23. Trimmed master termination

The resistors $R_{MASTER-BAT}$ and $R_{MASTER-INH}$ in parallel determine the master termination while the TJA1020 is in its modes: Standby, Normal-slope and Low-slope. In Sleep mode the master termination is determined by $R_{MASTER-BAT}$. Therefore the maximum LIN bus short-circuit current $I_{SC,max}$ can be trimmed by $R_{MASTER-BAT}$:

$$R_{MASTER-BAT} = \frac{V_{BAT,max}}{I_{SC,max}}$$

$$R_{MASTER-INH} = \frac{R_{MASTER-BAT} \times R_{MASTER}}{R_{MASTER-BAT} - R_{MASTER}} \text{ with } R_{MASTER} = 1\ k\Omega$$

4.4 Master termination for LIN networks with different supplied LIN nodes

In mixed-supplied LIN networks, where the supply of some slave nodes are ignition key controlled (clamp 15) while others are permanently connected to battery (clamp 30), unsupplied slave nodes (ignition key off) represent pull-down loads on the LIN bus. Thus it is recommended to apply the trimmed master termination (see Figure 23). With the trimmed master termination the pull-up during Sleep mode $R_{MASTER-BAT}$ can be adapted to the pull-down behavior of unsupplied slaves.

For the LIN bus an unsupplied TJA1020 represents in worst case a pull-down load of a diode with a forward biased voltage of V_{DS} = 2 V in series with a high-impedance resistor of R_S = 300 kΩ. Figure 24 shows an example of a mixed-supplied network with two unsupplied slave nodes with TJA1020 transceiver applied.

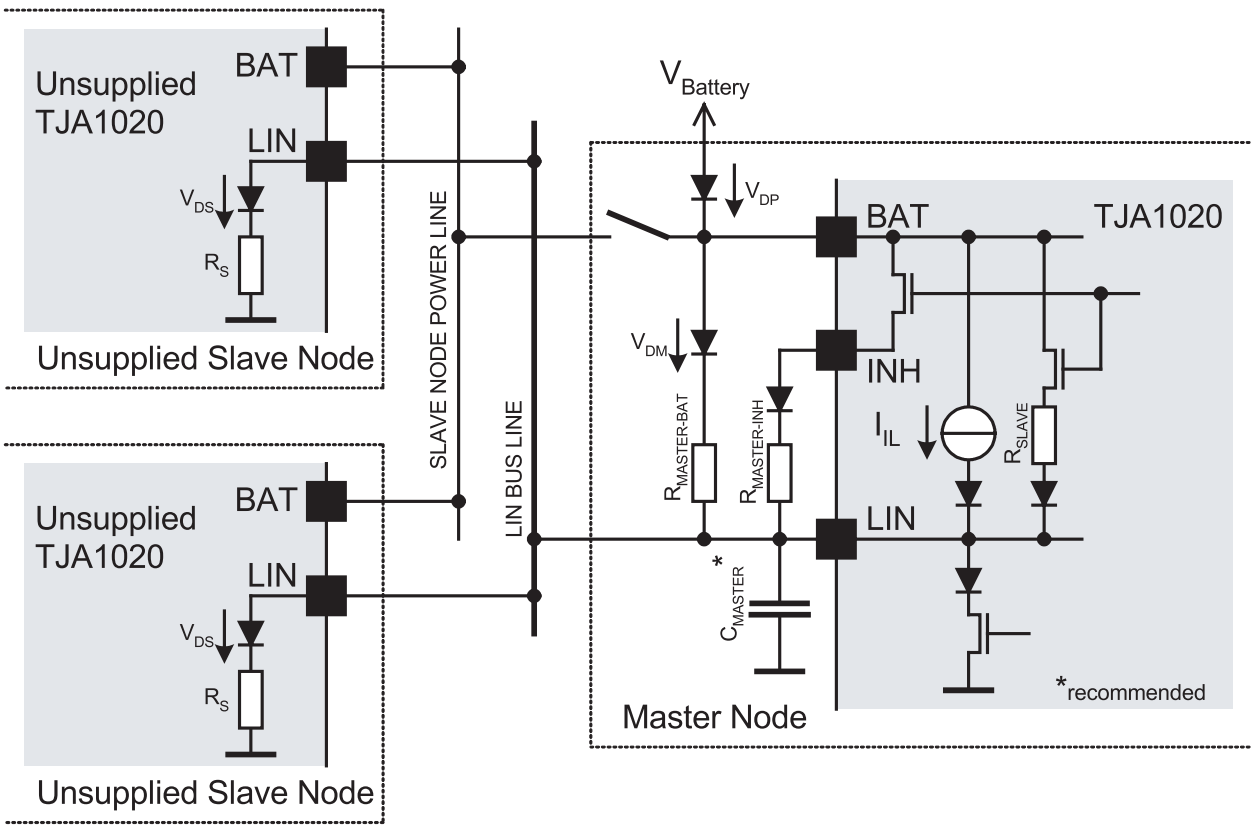


Fig 24. Different supplied slave nodes (simplified transceiver circuitry)

The maximum master termination resistor $R_{MASTER-BAT}$ can be calculated with the following equation:

$$R_{MASTER-BAT} \leq min\left(\frac{(V_{Battery} - V_{DP} - V_{DM} - V_{LIN,rec}) \times R_S}{V_{LIN,rec} - V_{DS} + R_S \times I_{LEAK}}\right) \times \frac{1}{N}$$, where $V_{DS} = 2\ V$ and $R_S = 300\ k\Omega$

with

V_{DP} = forward biased voltage of protection diode

V_{DM} = forward biased voltage of reverse current master diode

$V_{LIN,rec}$ = recessive LIN bus voltage

I_{LEAK} = leakage current from LIN bus to ground (e.g. plug leakage current)

N = number of unsupplied slaves nodes

Example: In a mixed-supplied LIN network with 2 unsupplied TJA1020 connected to the LIN bus it is assumed that both diodes, the protection diode as well as the reverse current diode, have a forward biased voltage of $V_{DP} = V_{DM} = 1$ V, and the recessive LIN bus voltage $V_{LIN,rec}$ shall remain above 0.75 V_{BAT} ($V_{BAT} = V_{Battery} - V_{DP}$). A LIN bus leakage current to ground of $I_{LEAK} \leq 10$ µA per unsupplied node is expected. Then for the battery voltage range of $V_{Battery} = 8$ V to 18 V the maximum master termination resistor is:

$$R_{MASTER-BAT} \leq min\left(\frac{(V_{Battery} - V_{DP} - V_{DM} - V_{LIN,rec}) \times R_S}{V_{LIN,rec} - V_{DS} + R_S \times I_{LEAK}}\right) \times \frac{1}{N} = 18\ k\Omega$$

5. EMC aspects

5.1 EME - network design hints

The LIN physical layer is a single-wire, wired AND bus with a battery related recessive level. Here, no compensation effect of the electromagnetic field is present as known from dual-wire concepts making use of differential signals (e.g. high-speed CAN). Thus a smooth output wave shaping becomes more important. The ElectroMagnetic Emission EME depends mainly on the falling and rising slope of the LIN bus waveform. The smoother these slopes are the more EME reduction can be achieved.

The TJA1020 provides a slope control adjustment by modifying the capacitive load (C_{MASTER} (Ref. 2) or C_{SLAVE} (Ref. 2)) on the LIN bus. The slope decreases with increasing capacitive load. Therefore increasing the total network capacitance ($C_{BUS} = C_{MASTER} + n \times C_{SLAVE} + C_{LINE}$ (Ref. 2)) can further reduce the EME. For very high bit rates close to 20 kBaud the LIN bus slope times have also impacts to system tolerances such as ground shift. Thus the time constant τ of the overall system shall not exceed its specified maximum τ_{max} (Ref. 2). Further it is not recommended to make use of the maximum allowed capacitive load $C_{BUS,max}$ (Ref. 2) at very high bit rates in order to keep some safety margin for the system.

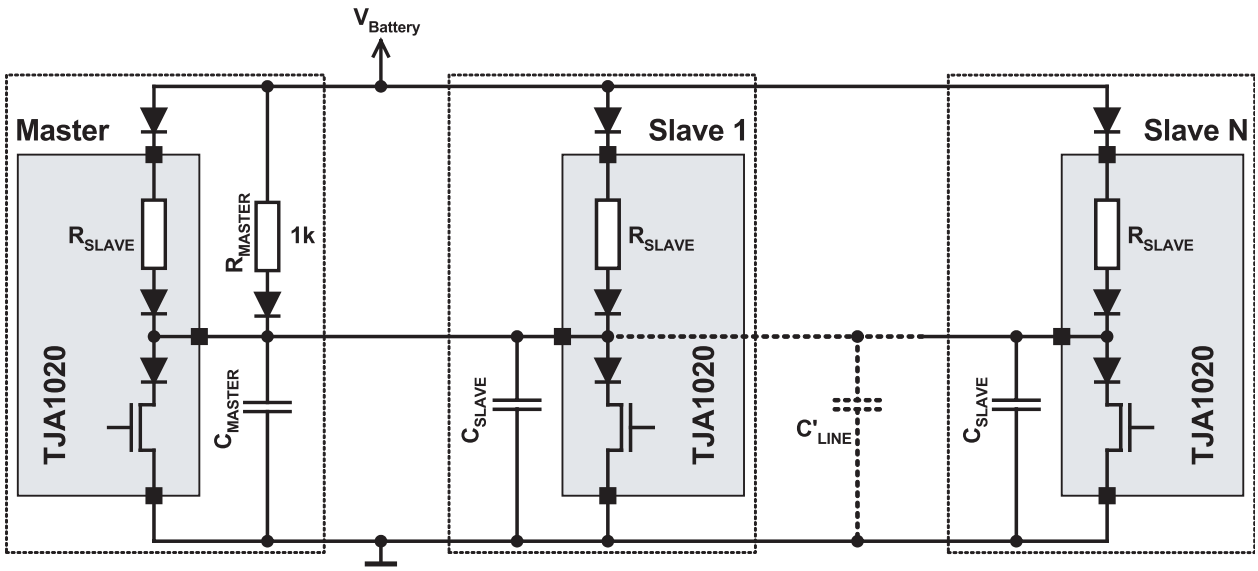


Fig 25. LIN network loads

In a LIN network the master resistor R_{MASTER} (Ref. 2) and the slave resistors R_{SLAVE} (Ref. 2) are accurately defined by the LIN standard (Ref. 2). No variation is allowed. Also the specified slave capacitance C_{SLAVE} (Ref. 2) provides almost no room for network optimizations. Only the master capacitor C_{MASTER} (Ref. 2) can be used to tune the LIN bus signal in either way.

For EME as well as for EMI a big network capacitance is of advantage. Thus the maximum master capacitance $C_{MASTER,max}$ is of interest. $C_{MASTER,max}$ can be calculated with following equations:

$$C_{MASTER,max} = \frac{\tau_{max}}{R_{BUS,max}} - N \times C_{SLAVE} - LEN_{BUS} \times C'_{LINE}$$ with

$$R_{BUS,max} = R_{MASTER,max} \| \frac{R_{SLAVE,max}}{N+1}$$

with

τ_{max} = maximum time constant of overall LIN network (Ref. 2)

$R_{MASTER,max}$ = maximum LIN master termination resistor (Ref. 2)

$R_{SLAVE,max}$ = maximum LIN slave termination resistor (Ref. 1)

C_{SLAVE} = LIN slave capacitance (Ref. 2)

C'_{LINE} = LIN bus line capacitance (Ref. 2)

LEN_{BUS} = overall bus line length (Ref. 2)

N = number of slaves nodes

Example: Assuming a 6-node LIN network with a capacitance of 220 pF per slave and an overall network length of 8 m with a line capacitance of 80 pF/m. It results in a maximum master capacitance of

$$R_{BUS,max} = R_{MASTER,max} \| \frac{R_{SLAVE,max}}{N+1} = 965\ \Omega$$

$$C_{MASTER,max} = \frac{\tau_{max}}{R_{BUS,max}} - N \times C_{SLAVE} - LEN_{BUS} \times C'_{LINE} = 3.44\ nF$$

In this example a master capacitor of C_{MASTER} = 3.3 nF is recommended.

5.2 EME - Low-slope mode

The curve shaping of the LIN bus signal in Normal-slope mode is optimized for the maximum specified LIN transmission speed of 20 kBaud. Thus for low speed LIN applications (e.g. 4.8 kBaud) the curve shaping in Normal-slope mode has unnecessary steep slopes. Therefore the TJA1020 provides the Low-slope mode (see Section 2.3.4) with reduced slopes (see Figure 10). These reduced slopes result in a further reduction of EME.

5.3 EMI - capacitive load

A capacitor on the LIN bus pin reduces the impact of RF-interferences. Thus it is recommended to provide a capacitor (e.g. $C_{MASTER/SLAVE}$ = 220 pF) from LIN to ground at each node.

6. ESD - aspects

6.1 General design hints for ESD levels beyond ±4 kV HBM

The on-chip ESD protection of pin LIN of the TJA1020 is designed to withstand $V_{esd(HBM)}$ = ±4 kV according to the Human Body Model (HBM) JESD22-A114-B (100 pF / 1.5 kΩ). External ESD protection on the LIN bus connection is recommended if the TJA1020 is subjected to ESD-pulses of more than $V_{esd(HBM)}$ = ±4 kV (Ref. 1) or if another ESD Model (e.g. IEC 61000-4-2 (Ref. 4)) is applied. Figure 26 shows a set-up for such external ESD protection.

The clamping voltage V_{CLAMP} of the ESD protection diodes should be chosen above the maximum battery voltage in order not to be damaged, in case the LIN bus line is shorted to the battery line. Furthermore, the positive clamping voltage $V_{CLAMP-POS}$ should be below the maximum LIN bus voltage $V_{LIN,max}$ = 40 V (Ref. 1) and the negative clamping voltage $V_{CLAMP-NEG}$ should be above the minimal LIN bus voltage $V_{LIN,min}$ = −27 V (Ref. 1).

According to the LIN Specification Rev. 1.3 (Ref. 2), the LIN slave node capacitance shall be less than $C_{SLAVE,max}$ = 250 pF to ground. Together with the inherent capacitance of an ESD-protection device (e.g. suppressor diode) this requirement (< 250 pF) must be fulfilled.

The ferrite $L_{FERRITE}$ between LIN capacitor and the ESD protection diodes serves for minimizing the current of the first ESD peak.

The suppressor diodes D_{POS} and D_{NEG} should be placed as close as possible to the connectors, whereas the LIN node capacitor $C_{MASTER/SLAVE}$ and the ferrite $L_{FERRITE}$ should be placed close to the LIN transceiver's bus pin.

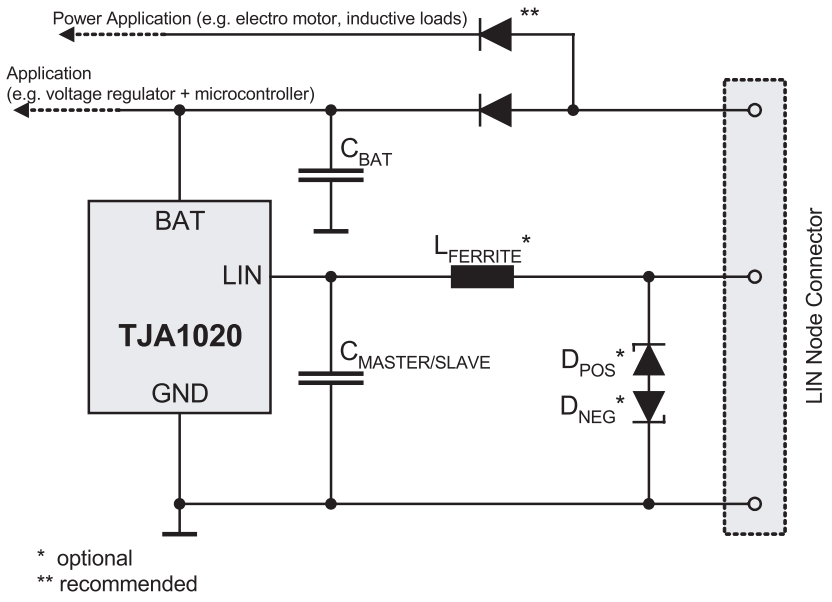


Fig 26. External ESD-protection set-up

6.2 ESD protection example for ESD model according to IEC 61000-4-2 (Ref. 4)

The maximum peak current an ESD protection diode has to withstand depends on the maximum ESD voltage and the applied ESD model. Thus, with a capacitor of 150 pF charged to 10 kV and a discharge resistor of 330 Ω a theoretical peak current of 30 A occurs. The discharge time constant will be about 50 ns.

Table 3 shows the ESD results achieved with the respective proposed protection elements. The protection is based on the ESD protection diode PESD1LIN (Ref. 5), which is especially designed to fulfill the demands of LIN bus lines. The PESD1LIN contains the two diodes D_{POS} and D_{NEG} (see Figure 26) in one package. In Table 3 V_{ESD} corresponds to the ESD voltage the TJA1020 withstands without being damaged.

Table 3: ESD voltage the TJA1020 withstands without being damaged

Applied components				V_{ESD} (150 pF / 330 Ω)
$C_{MASTER/SLAVE}$	$L_{FERRITE}$	D_{POS}	D_{NEG}	
-	-	PESD1LIN (Philips)		±5.0 kV
-	BLM18BD102SH1 (muRata)	PESD1LIN (Philips)		±7.5 kV
-	MMZ1608Y102B (TDK)	PESD1LIN (Philips)		±7.0 kV
220 pF	-	PESD1LIN (Philips)		±5.5 kV
220 pF	BLM18BD102SH1 (muRata)	PESD1LIN (Philips)		±7.5 kV
220 pF	MMZ1608Y102B (TDK)	PESD1LIN (Philips)		±7.0 kV
220 pF	MMZ2012Y202B (TDK)	PESD1LIN (Philips)		±8.5 kV

7. Transceiver control

The modes of the TJA1020 are controlled by the pins NSLP and TXD. The following chapters describe the mode control of TJA1020 and how to deal with LIN bus failures.

The transceiver control can be split into two basic applications:

- The microcontroller power supply is controlled via the INH pin of the TJA1020
- Independent of the TJA1020's modes the microcontroller is permanently supplied

7.1 INH controlled microcontroller power supply

After a local or remote wake-up the Standby mode is entered automatically. As a result the INH pin outputs a battery related high level and thus switches on the external voltage regulator. In consequence the microcontroller becomes supplied and starts with its initialization. The TJA1020 indicates the wake-up event by an active low at RXD.

Depending on the use of the NWAKE pin two different software-flows for mode control are recommended:

7.1.1 Applications using NWAKE

The TJA1020 allows distinguishing between different wake-up sources using the TXD pin. Thus the TXD pin needs to be applied with a pull-up behavior as described in Section 3.2.2. This pull-up behavior is required to sense the TJA1020's pull-down transistor at TXD, which becomes active after a local wake-up event via NWAKE. Thus the wake-up source can be distinguished by reading the TJA1020's TXD pin.

To distinguish between Normal-slope mode and Low-slope mode the TJA1020's TXD pin is used. The Normal-slope mode is entered if TXD carries a high level after NSLP is set high. TXD gets high automatically after a local wake-up event if the corresponding microcontroller port pin is configured to be input (weak high) because the wake-up source information is cleared immediately with setting NSLP to high level. The mode change itself is performed holding NSLP high for at least $t_{gotonorm}$ (Ref. 1) (see also the timing in Figure 9).

Remark: There is no software timing constraint required for setting the microcontroller port pin TX to high output after setting NSLP to high, because the local wake-up source information at TXD is cleared immediately with setting NSLP to high level, whereas the mode transition itself executes after $t_{gotonorm}$ (Ref. 1).

To enter the Low-slope mode the microcontroller TX port pin is simply set low before the NSLP input pin of the TJA1020 gets a high level.

Figure 27 shows the related software flow of a Standby to Normal/Low-slope transition.

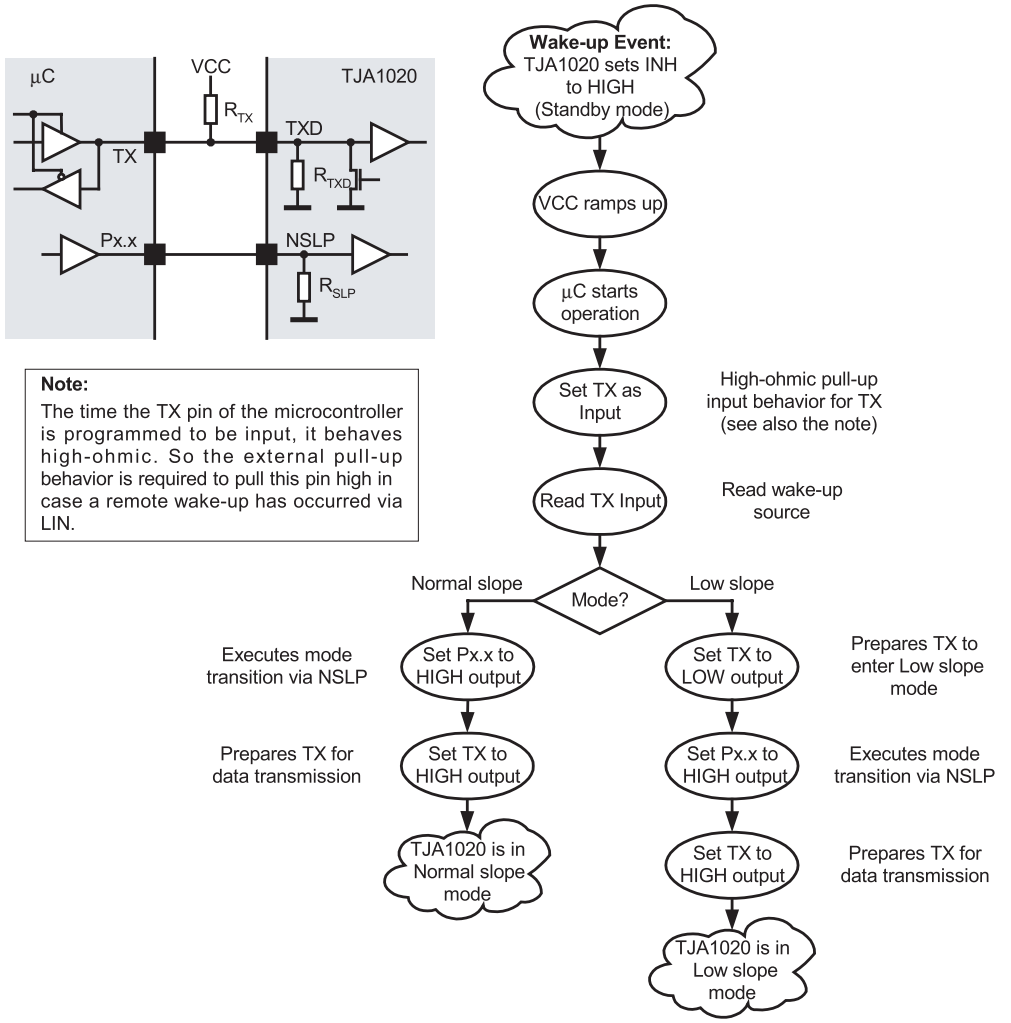


Fig 27. Flow diagram of Standby to Normal/Low-slope transition, using NWAKE

7.1.2 Applications without using NWAKE

In case no local wake-up source is present the hardware becomes simpler because the TXD pin of the TJA1020 behaves as input only. Thus the weak pull-up behavior as described in Section 7.1.1 is not required.

The software flow is shown within Figure 28. Here the TXD input of the TJA1020 defines the next mode before the NSLP input is set to a high-level.

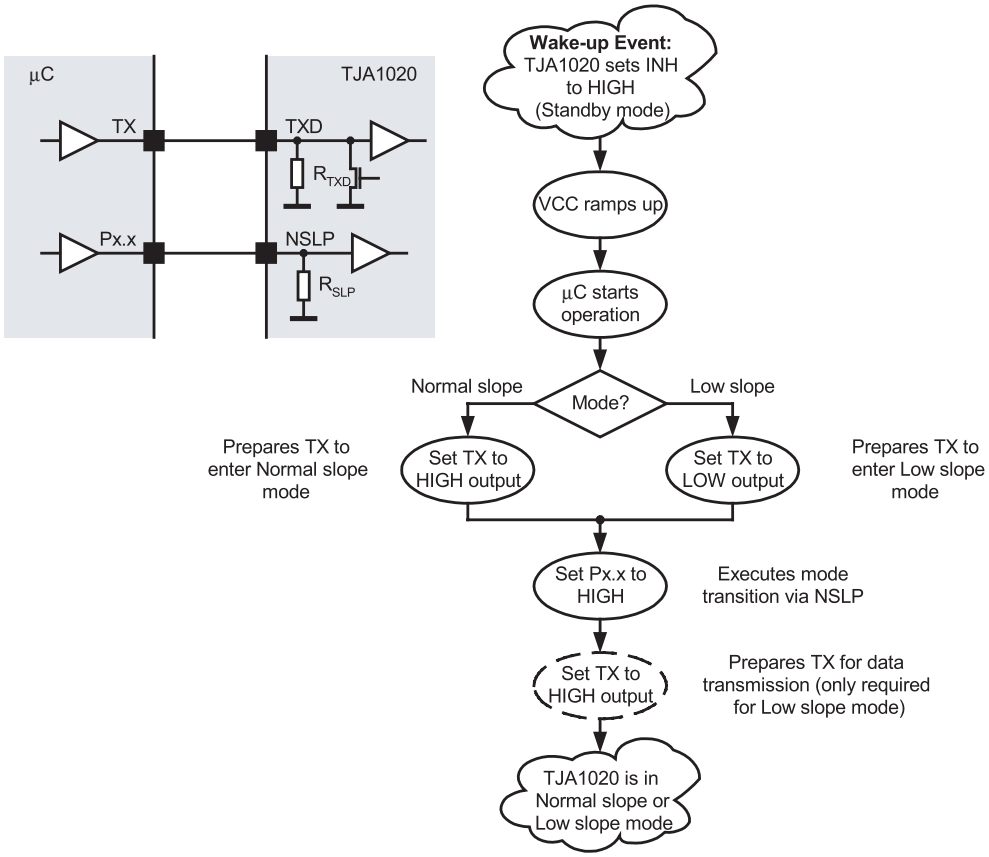


Fig 28. Flow diagram of Standby to Normal/Low-slope transition, NWAKE not used

7.2 Permanently supplied microcontroller

In some applications the TJA1020 is not used to control the power supply of the microcontroller. Thus the INH pin is unused, respectively used for another purpose. For such applications the TJA1020 allows a direct transition from Sleep mode into Normal-slope mode or Low-slope mode.

Depending on the use of the NWAKE pin two different software-flows for mode control are recommended:

7.2.1 Application using NWAKE

Here the same flow is used as described within Section 7.1.1. The only difference is that no initialization phase is performed, because the microcontroller is already running. Figure 29 shows the related software flow diagram with respect to the pin description of TXD in Section 3.2.2.

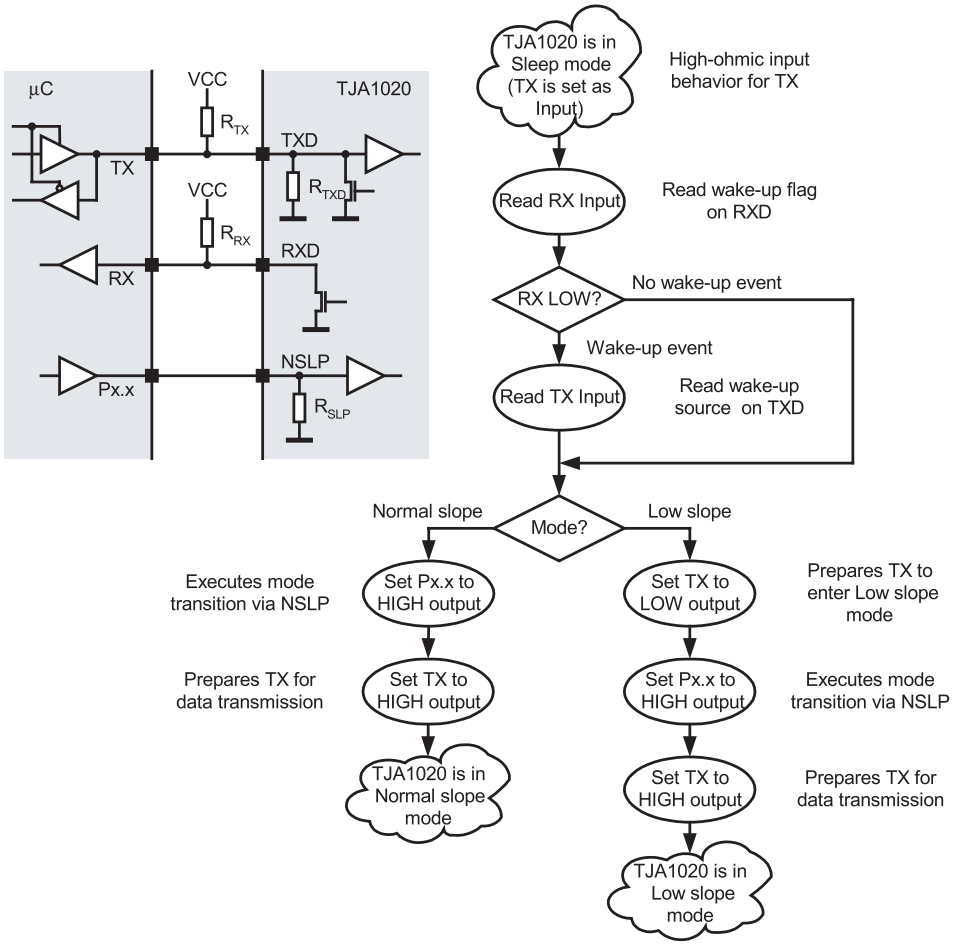


Fig 29. Flow diagram of Sleep to Normal/Low-slope transition, using NWAKE

7.2.2 Application without using NWAKE

Here the same flow is used as described within Section 7.1.2. The only difference is that no initialization phase is performed, because the microcontroller is already running. The corresponding software flow diagram is shown in Figure 30.

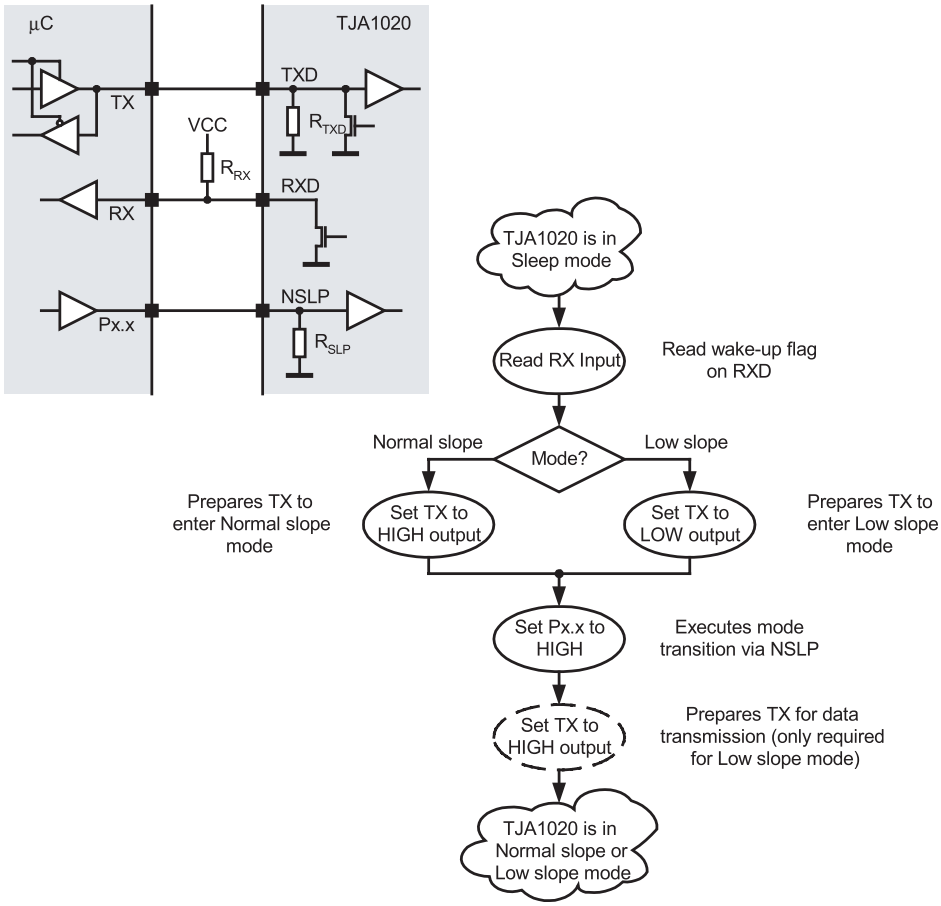


Fig 30. Flow diagram of Sleep to Normal/Low-slope transition, NWAKE not used

7.3 Transition from Normal-slope/Low-slope into Sleep mode

The TJA1020 enters its Sleep mode if the NSLP input is becoming low for at least $t_{gotosleep}$ (Ref. 1).

Depending on the use of the NWAKE pin two different software-flows for mode control are recommended:

7.3.1 Application using NWAKE

If the NWAKE input of the TJA1020 is in use, the microcontroller port pin (e.g. TX) driving the TXD pin of the TJA1020 should be configured as input or bi-directional before the mode transition is executed by setting a low level on NSLP. This provides pull-up behavior at pin TXD in case of wake-up events via NWAKE during mode transition towards Sleep mode. Figure 31 shows the software flow diagram of a transition from Normal-slope mode or Low-slope mode into Sleep mode with NWAKE support.

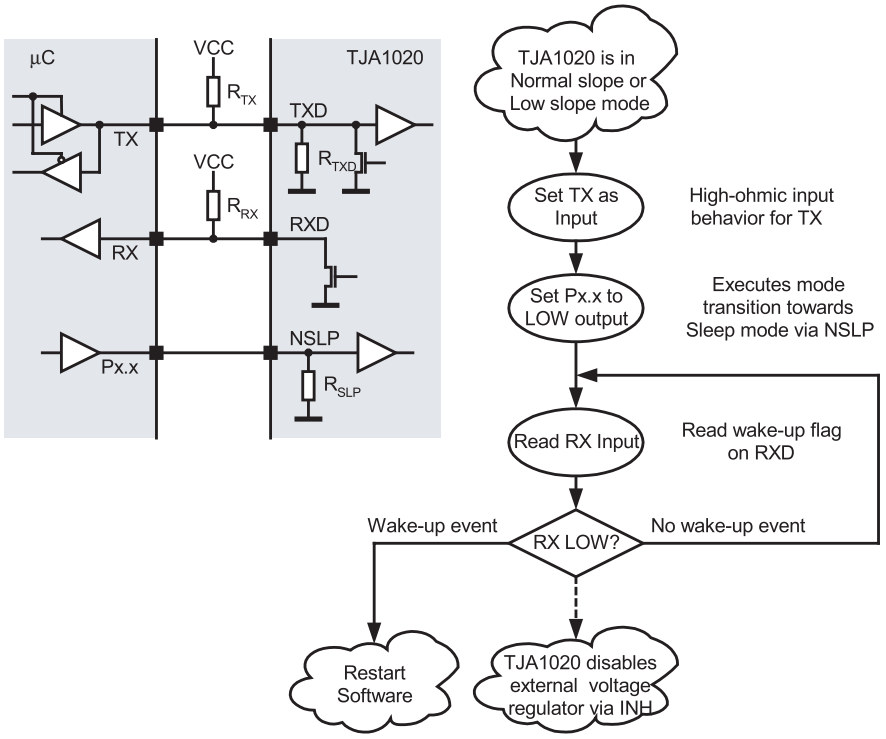


Fig 31. Flow diagram of Normal/Low-slope to Sleep transition, using NWAKE

7.3.2 Application without using NWAKE

In case the NWAKE pin is unused and no TXD pull-up behavior is provided (see also Section 3.2.2.1), only the NSLP input should become low (see Figure 32). The 'Set TX as input' step within the software flow diagram in Figure 31 should not be performed, since the weak pull-down R_{TXD} (Ref. 1) would cause a low level on TXD if the microcontroller port pin TX is set into a high-impedance state without pull-up behavior. This would result in a dominant level on the LIN bus until NSLP is set low or the TXD dominant time-out phase is passed. Instead it is recommended to set TXD to high level via the microcontroller port pin (e.g. TX).

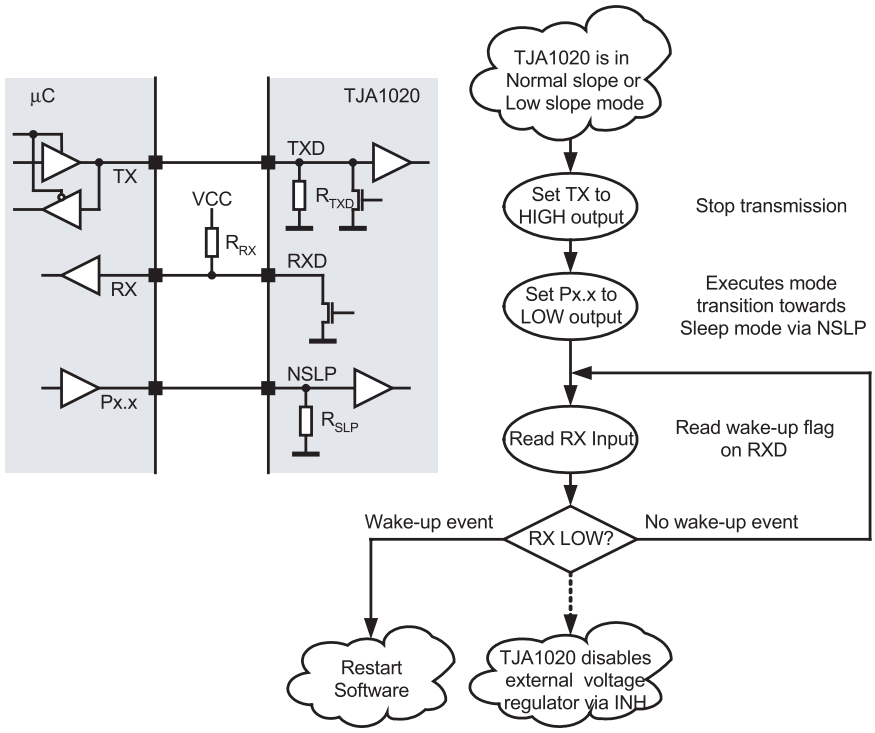


Fig 32. Flow diagram of Normal/Low-slope to Sleep transition, NWAKE not used

8. Failure management

8.1 LIN bus short-circuit to ground

In case the LIN bus is shorted to ground a continuous current flows out of V_{BAT} due to the LIN termination. The TJA1020 allows to reduce this short-circuit current to a minimum using its integrated termination control.

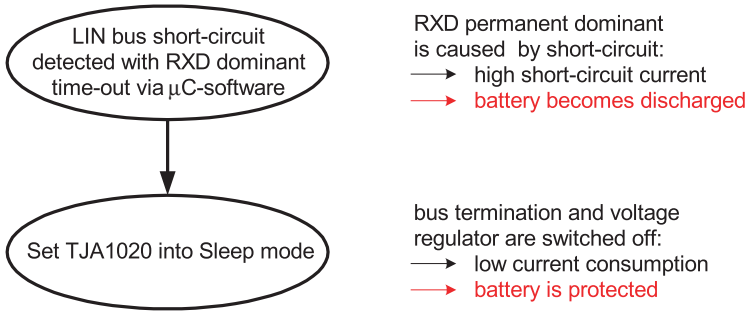


Fig 33. Failure management if LIN bus is shorted to ground

Once the LIN bus is shorted to ground this can be detected in software monitoring the continuous dominant level on RXD.

In order to reduce this failure current the TJA1020 is simply put into its Sleep mode, if not needed anymore. This results in disabling the slave termination resistor R_{SLAVE} (Ref. 1) as well as the external master termination resistor R_{MASTER} if connected to INH. Only an internal weak pull-up current source $I_{IL(LIN)}$ (Ref. 1) remains active for the case of a LIN bus failure recovery. So the INH-controlled master termination resistor R_{MASTER} optimizes the system with respect to fail-safe behavior. Thus the system enters its Low-power mode (V_{CC} off). The remaining short-circuit current is the amount of the internal bias current and the pull-up current source $I_{IL(LIN)}$ (Ref. 1). Figure 33 shows the corresponding failure management flow.

8.2 TXD dominant failure

Usually in case a TXD pin is shorted to ground, the LIN bus is clamped to the dominant level and therefore overrules any transmission on the LIN bus. To protect the LIN bus from being continuously driven to the dominant level, the TJA1020 has an integrated TXD dominant timer. Thus the transmitter of the TJA1020 is disabled, if a TXD dominant failure is detected and the LIN bus is released again.

Due to the integrated pull-down TXD resistor R_{TXD} (Ref. 1), an open TXD pin results also in a continuous dominant situation. In such a case the TXD open failure is detected by the integrated TXD dominant timer and disables the transmitter stage of the TJA1020.

Both failures, the TXD dominant failure as well as the TXD open failure, are detected, if the TXD input maintains dominant for at least t_{DOM} (Ref. 1). As a consequence the LIN transmission speed is limited to a minimum baud rate. Its calculation is shown in Section 8.3.

Furthermore if one of the above failures is present, a change of the NSLP input signal does not modify the TXD dominant timer state and therefore makes sure that no dominant LIN signal is driven to the bus by the TJA1020 (fail-safe behavior).

8.3 Minimum baud rate and maximum TXD dominant phase

Due to the TXD dominant failure detection of the TJA1020 the maximum TXD dominant phase is limited by the minimum TXD dominant time-out time t_{DOMmin} (Ref. 1). As a consequence the transmission speed is also limited to a minimum baud rate.

8.3.1 Minimum baud rate of a master node

The maximum dominant phase of the LIN protocol (Ref. 2) is the maximum SYNCH BREAK LOW PHASE $T_{SYNBRK,max}$ (Ref. 2) of the SYNCH BREAK FIELD. The SYNCH BREAK FIELD is part of the message frame HEADER, which is only sent by the master node. The maximum SYNCH BREAK LOW PHASE $T_{SYNBRK,max}$ (Ref. 2) represents the maximum number of dominant bits sent by the master. Depending on the length of the maximum SYNCH BREAK LOW PHASE $T_{SYNBRK,max}$ (Ref. 2) and the minimum TXD dominant time out time t_{DOMmin} (Ref. 1) the minimum baud rate for the master node can be calculated by the following equation:

$$baudrate_{min,MASTER} = \frac{T_{SYNBRK,max}}{t_{DOM,min}}$$

with $T_{SYNBRK,max} > T_{SYNBRK,min}$

where $T_{SYNBRK,min}$ is specified in (Ref. 2)

Thus with a maximum SYNCH BREAK LOW PHASE of $T_{SYNBRK,max}$ = 14.4 the TJA1020 allows operating within master application down to 2.4 kBaud.

8.3.2 Minimum baud rate of a slave node

A slave node sends the RESPONSE part (Ref. 2) of the LIN message frame only, which has a maximum dominant phase of 9 bits (start bit + 8 data bits). As a result the minimum baud rate of a slave can be calculated by the following equation:

$$baudrate_{min,SLAVE} = \frac{9 + n_{safe}}{t_{DOM,min}}$$

with n_{safe} as safety margin

Thus with a safety margin of n_{safe} = 1.8 the TJA1020 allows operating within slave application down to 1.8 kBaud.

9. Power consumption

During design of the TJA1020 special care has been taken on system power consumption since this is a key for introduction of this new LIN sub bus system within automotive applications. The TJA1020 achieves lowest power consumption not only within a failure free system but also during bus failure situations on the LIN bus line.

Even with the extremely low system power consumption the TJA1020 provides full wake-up capability via the LIN bus as well as via local events keeping a high immunity against electromagnetic disturbances.

9.1 Sleep mode power consumption

The TJA1020 provides very low power consumption in Sleep mode. If the transceiver is used to control the ECU supply via INH pin the only remaining system current flows into the BAT pin ($I_{BAT(sleep)}$ (Ref. 1)). All other pins do not sink or source any extra current (see Figure 34).

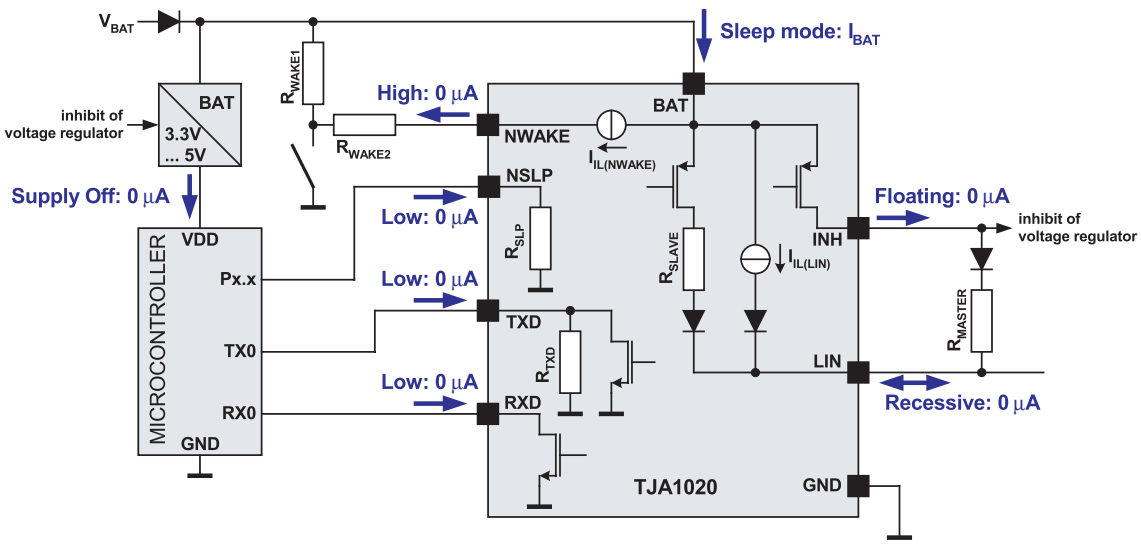


Fig 34. Current consumption in Sleep mode

9.2 Sleep mode power consumption at presence of LIN bus short-circuit

In case of a LIN short-circuit to ground the power consumption of the TJA1020 keeps also very low if the Sleep mode is selected. Since the termination of the system becomes nearly disabled during Sleep, the resulting short-circuit current is defined by the internal bias current and the remaining pull-up current source for failure recovery (see Figure 35).

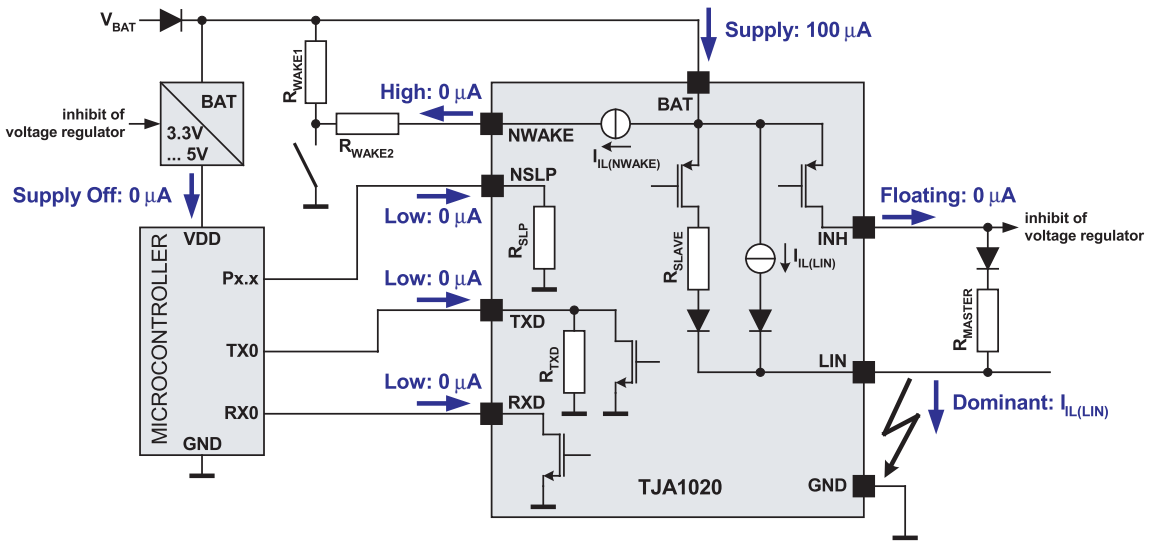


Fig 35. Typical short-circuit current consumption in Sleep mode

10. References

[1] Data Sheet TJA1020, LIN Transceiver, Philips Semiconductors, Jan. 2004

[2] LIN Specification Package, LIN Protocol Specification – Revision 1.3, LIN Consortium, Dec. 2002

[3] International Standard ISO 9141, Road Vehicles – Diagnostic Systems – Requirement for Interchange of Digital Information, International Standardization Organization, 1989

[4] International Standard IEC 61000-4-2, Electromagnetic Compatibility – Testing and Measurement Techniques – Electrostatic Discharge Immunity Test, International Electrotechnical Commission, 2001

[5] Data Sheet PESD1LIN, LIN Bus ESD Protection Diode, Philips Semiconductors, Oct. 2004

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